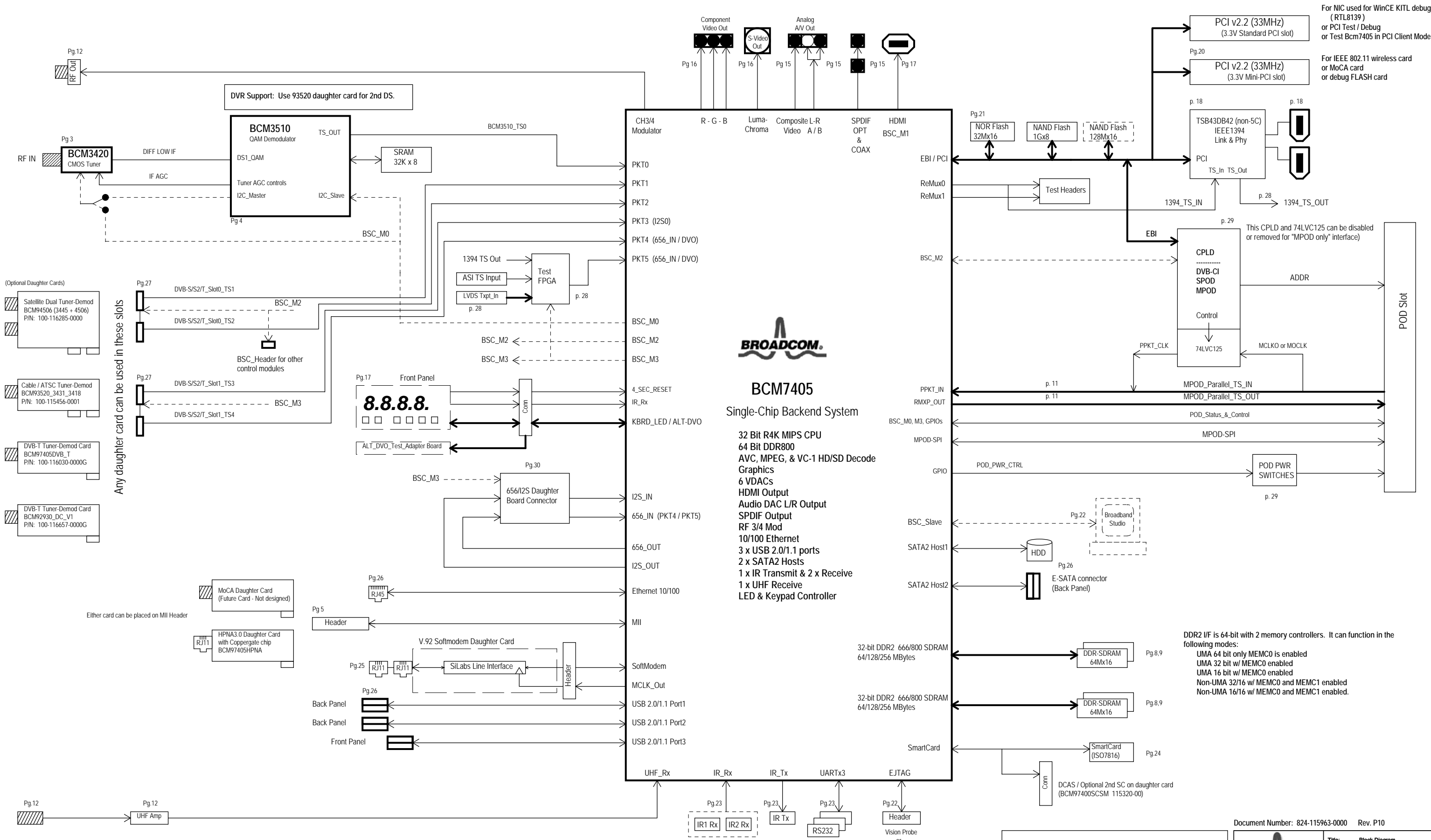


# BCM97405 AVC/MPEG/VC-1 HD/SD, Graphics, Digital PVR, IP/Satellite/DVB-C,T Set Top Box



## ECOs:

ECO BCG-02008: V00 Rev. P1:  
- Initial Release

ECO BCG-02042: V00 Rev. P2 changes:  
- Pg 28 Changed J1307 to RoHS part.

ECO BCG-02086: V00 Rev. P3 changes:  
- Pg 13 Moved RD1306, RD1328 to Position A.  
(Selects correct DRAM size for MEMCO/1)  
- Pg 22 Moved RD2201 to Position B  
(Enables EJTAG.)  
- Pg 19 Stuff RN1904, RN1905 with 0 ohms (528499-00)  
(Connect SLOT1 and Transport FPGA to PKT4 and PKT5.)  
- Pg 30 Remove RN3001  
(Disconnect PKT5 from I2S output of VDEC-VEC daughter card.)  
- Pg 26 Change C2609 to 100pf (500569-00)  
Change R2617 to 4K 1% (502672-00)  
(Correct USB RRef.)

ECO BCG-02114: V00 Rev. P4:  
-Agile documentation correction. No impact on schematic.

ECO BCG-02143: V00 Rev. P5:  
-Pg 11 Swap SDA and SCL for BSC\_M0.2,3 busses  
-Pg 13 Replace resistor straps RD1303, RD1304, RD1324 with 3-pin jumpers  
for DDR\_Configuration.  
-Pg 30 Remove RN3014 and stuff RN3012, RN3013  
with 0 ohm rpacks 528499-00.  
(Enables PKT\_VALID[5:0], PKT\_ERROR[5:4],  
disables 656 out of J3001:

ECO BCG-02213: V00 Rev. P6:  
- New PCB spin. Includes all previous revisions plus:  
-Pg 08 Add 20 DDR test pads. Place them close to 7405.  
Move old TP's over by DDR chips.  
-Pg 09 Replace Micron DDR2-667 RAM with Samsung DDR2-800  
-Pg 11 Swap SDA and SCL for BSC\_M1 bus  
-Pg 13 Replace resistor straps RD1308, RD1310, RD1322 with 3-pin jumpers  
for Flash/ROM Size1, Flash Type, USB Mode  
Change strapping for CPU frequency to 405 MHz  
-Pg 32 Add D5.0V to J216-1 heatsink fan connector.  
Move TP218, TP225 out of POD path. Distribute GND TP's better.  
-Pg 37 DNI backup power regulators

ECO CORP-06712: V00 Rev. P7:  
-BRCM p/n 502858-00 CAP,CER,0603,0.1uF,20%,16V,X7R) will be made  
obsolete as it is a duplicate of the BRCM p/n 520192-00. This ECO will update all  
BOM that currently used 502858-00 and update with 520192-00.

ECO BCG-02417: V00 Rev. P8:  
-Pg 03 Change C526, C527 from 1000pf to 27pf. (Fixes slow rise time on BSC\_M0.)  
-Pg 08 Change R804 to 150 ohms (Fixes RCOMP)  
-Pg 21 Replace U2105 with 8Gb NAND Flash  
-Pg 22 Change various R and C values in 3OT Crystal circuit.  
-Pg 26 Change R2609 from 1k to 1.24k.  
Remove R2605, R2606, R2607, R2608 (E-net PHY already terminated on die)  
-Pg 32 Short pins 9, 12 together on U202. (Connects AVIN to PVIN on ER5336Q1.)  
-Pg 32-33 Corrected Red TP's from 531213-00 to 521741-00.  
-Pg 20, 21, 25, 29 Changed 0.1uf caps to 520193-00 to be same as those on Pg 4.  
The following changes were made to the schematic:  
-Pg 10, 11, etc. Multi-function pin names on Bcm7405 symbol corrected.  
-Pg 13 Corrected strapping table:  
"strap\_ebi\_rom\_size" settings for NAND ECC inverted  
"strap\_ebi\_boot\_memory" added info for NAND WR-protect.  
-Pg 32, 33 Amperage and Power numbers corrected.  
Updated / corrected notes on several pages.

ECO BCG-03062: V00 Rev. P9:  
-Pg 04 Change Y601 to 28 MHz (for high-symbol-rate QAM)  
-Pg 10 GND RN1025-1,2,3,4 to prevent POD VPP enables from floating.  
Remove RN1026, RN1027 to disconnect UART stubs on MII lines.  
Add 0 ohm to R1016 to connect MII\_TX\_ERR.  
-Pg 10,30 Remove R1022, add jumper to move 3510 IRQ from GPIO\_015 to GPIO\_024.  
-Pg 17 Remove C1708, the 56pf cap on HDMI CEC line.  
-Pg 21 Remove R2169 to disable Block Lock on NAND flash.  
-Pg 23,24,29 Remove R2301, R2302, R2909 and jumper UART0 Rx/Tx to GPIO\_111/112.  
Jumper POD\_VCC\_ON to GPIO\_110.  
The following changes were made to the schematic:  
-Pg 16 Change 30 MHz filter name to "elliptical".  
-Pg 22 Change EJTAG note.  
-Pg 24 Add NDS note.  
Other minor note changes.

ECO BCG-03757: V00 Rev. P10:  
-Pg 08 Change PCOMP, NCOMP terminations (R805, R806) to 24.3 ohms  
-Pg 09 Change DDR\_CLK terminations to Thevenin (PU/PD)  
Change all VTT terminations to 62 ohms.  
The following changes were made to the schematic:  
-Pg 08 Revise DDR2 layout rules.  
-Pg 26 Add note to use 25-30MHz backup SATA crystal  
Add note to leave E-Net termination pads on board  
Add note to add 1k differential terminations to SATA lines.  
-Pg 34 Add note that C114 not needed now that RFM\_PLLCAP is just a test port.

## Errata:

-Pg 05 Add MICTOR connector to MII lines for logic analyzer.  
-Pg 15 Consider using MAX9722 for audio opamps. (for pop suppression)  
-Pg 19 Add RMX\_PAUSE0/1 to Remux connectors. Stuff DNI'd resistors to enable these paths.  
-Pge 21 Add skl footprint for testing various NAND Flash (see Emulation Technology)  
-Pg 26 eSATA & E-net ports need ESD protection.  
Add 25-30MHz SATA xtal footprint.  
Change SATA connectors to SMT.  
-Pg 32 Split 1.8v power so DDR and 7405 can be measured separately.  
Add GND puddle on Layer 5 under DDR address and data traces on Layer 6.  
Replace Enpirion regulator with another brand.

## Page Index

BCM97405MBV00
01: Block Diagram
02: Revision History
03: Downstream Tuner 0 (3420)
04: BCM3510
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07: Blank
08: DDR Term/Conn
09: 64-bit DDR2 SDRAM
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13: Pin Strapping
14: PKT_In, RMXP_Out, SPI
15: Ana Audio, SPDIF, I2S_I/O
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19: PKT, RMX
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31: Test Connector & ARC UARTs
32: Power Supply Regulation
33: Power Supply Regulation
34: BCM740X Analog Decoupling
35: BCM740X Digital Decoupling
36: Stack-up & Impedance Model
37: Backup Power Supplies



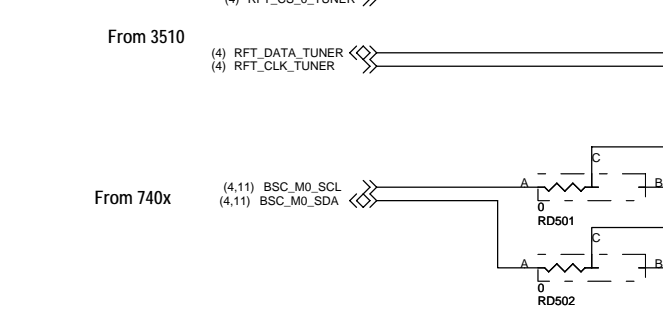
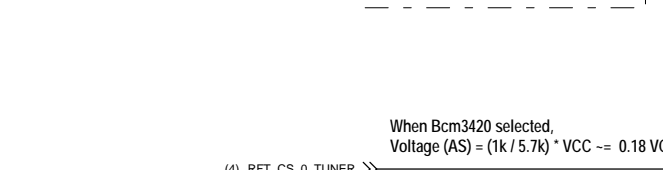
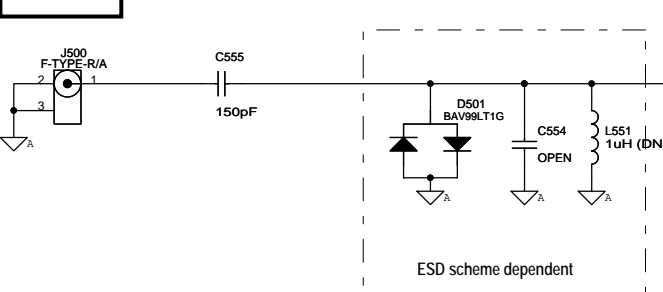
Title: Revision History / Index  
Document: BCM97405MBV00 Schematic  
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Modified: Thursday, June 19, 2008  
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**NOTES:**

1. BCM3420 tuner is an HVQFN40 package with downset paddle.
2. Clear solder mask from all top/bottom GND.
3. Use 1 oz copper.
4. Use the shortest trace for low value capacitors.
5. Make provisions for shielding the entire tuner section.
6. Plated through hole (PTH) vias should be covered by solder mask to prevent molten solder wicking into the vias.

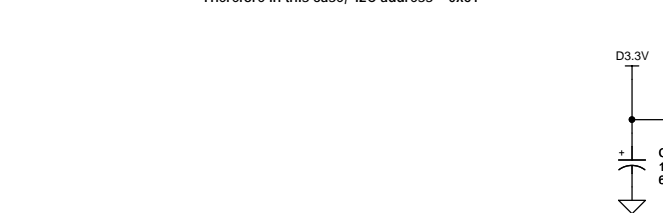
CABLE IN



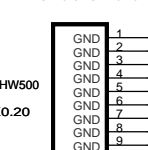
When Bcm3420 selected,  
Voltage (AS) =  $(1k / 5.7k) * VCC \approx 0.18 VCC$

MA1	MA0	Voltage Applied on AS Input
0	0	0V to 0.1 x V <sub>CC</sub>
0	1	Open or 0.2 x V <sub>CC</sub> to 0.3 x V <sub>CC</sub>
1	0	0.4 x V <sub>CC</sub> to 0.6 x V <sub>CC</sub>
1	1	0.9 x V <sub>CC</sub> to 1.0 V <sub>CC</sub>

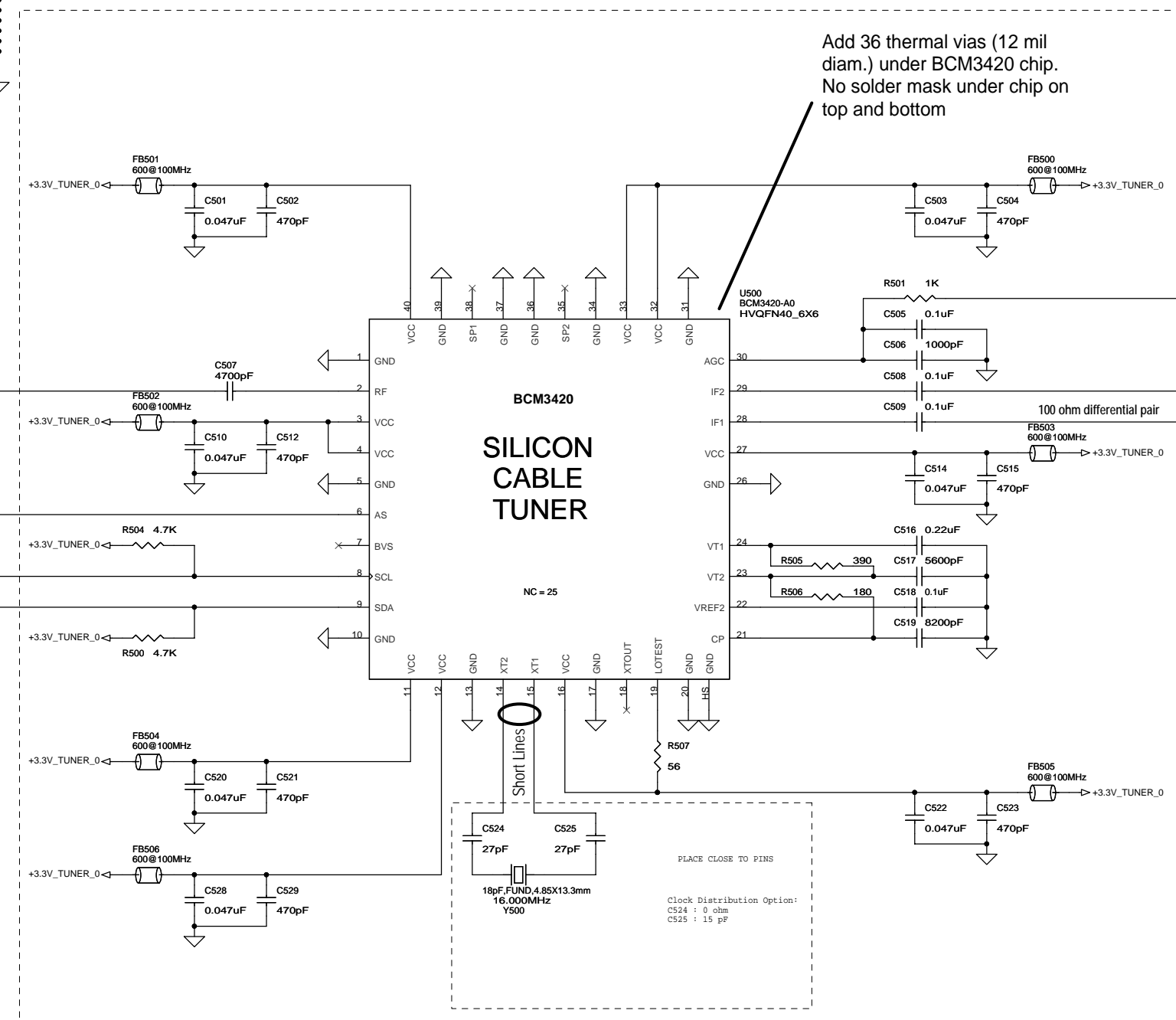
Therefore in this case, I2C address = 0x61



**Shield for Tuner**

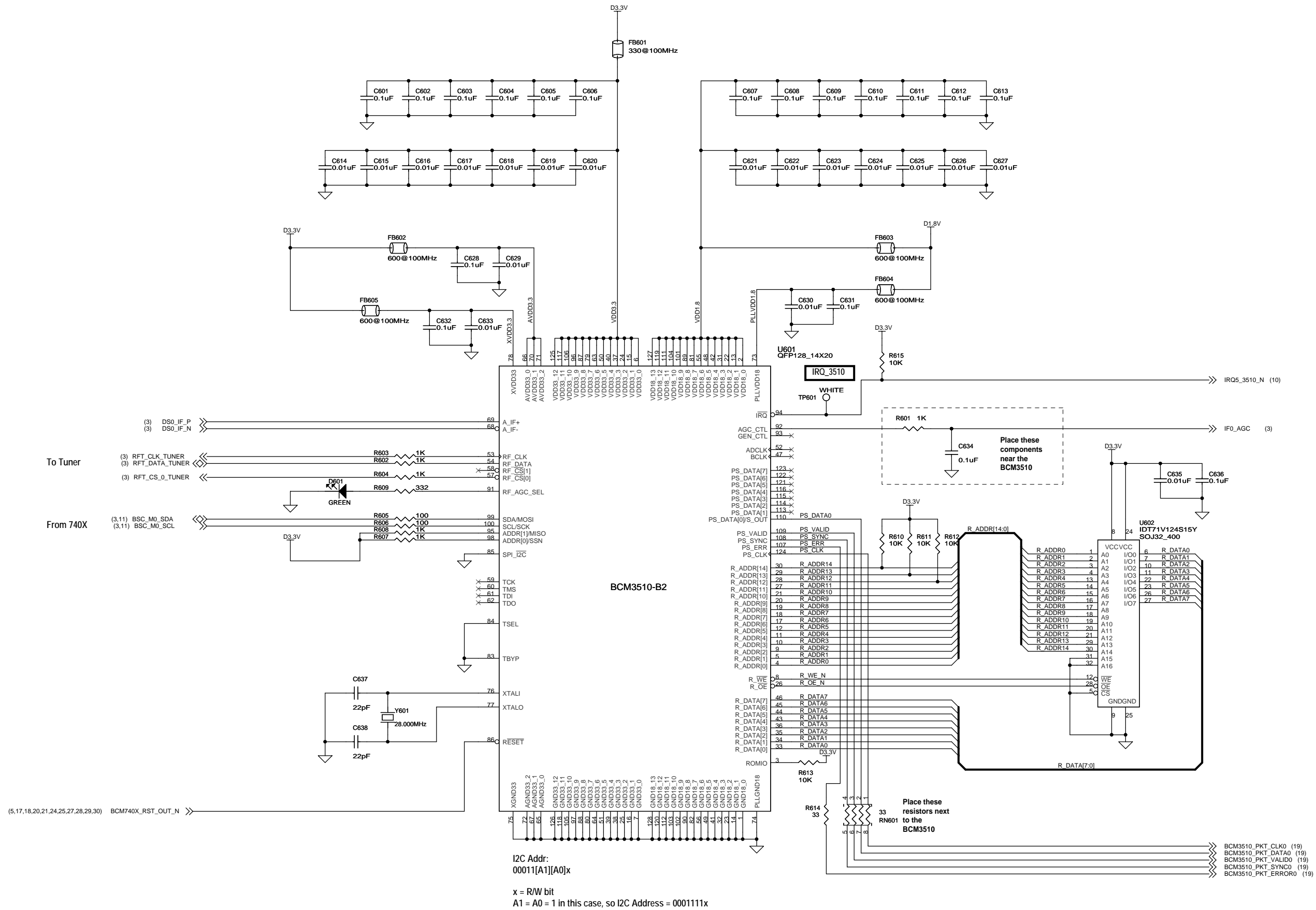


**THESE COMPONENTS ARE WITHIN THE SHIELD OUTLINE**



**Cable Tuner XTAL Specifications:**

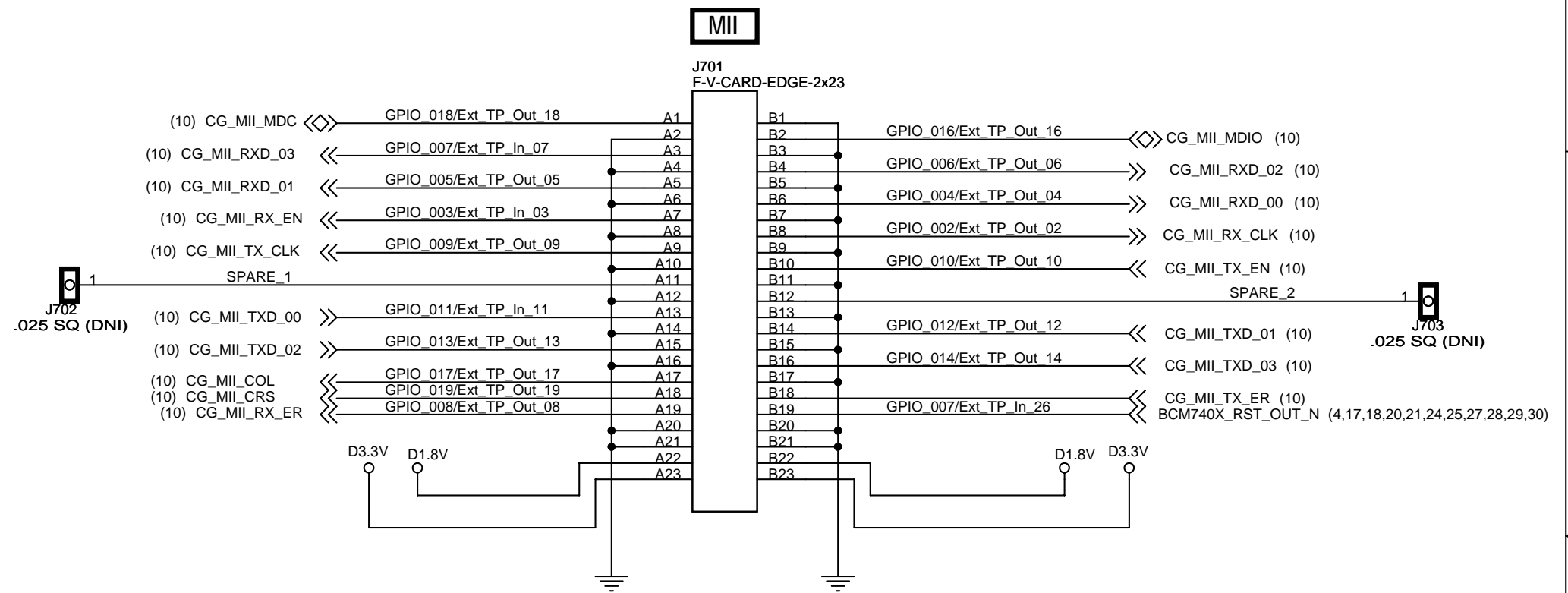
- Fundamental at 16.00 MHz
- Load capacitance: 18.0 pF
- ESR: 50 Ohms Max.
- Tolerance: +/- 50 ppm
- Stability: +/- 100 ppm



To Tuner  
From 740X

I2C Addr:  
00011[A1][A0]x  
x = R/W bit  
A1 = A0 = 1 in this case, so I2C Address = 0001111x

BCM3510\_PKT\_CLK0 (19)  
BCM3510\_PKT\_DATA0 (19)  
BCM3510\_PKT\_VALID0 (19)  
BCM3510\_PKT\_SYNC0 (19)  
BCM3510\_PKT\_ERROR0 (19)



MII Daughter Card Connector for HPNA and MoCA.  
 Important: Each signal must have an adjacent GND pin.

MII Speed: 50 MHz x 4 lines = 200 Mbits/sec

Add an unplated mounting hole for the daughter card L bracket. Hole size for 4-40 screw.



Title: Coppergate HPNA  
 Document: BCM97405MBv00 Schematic  
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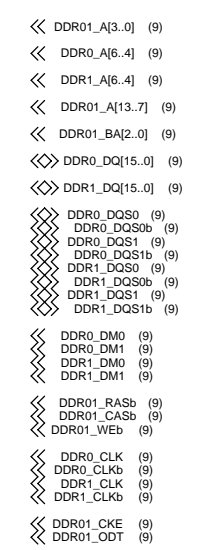
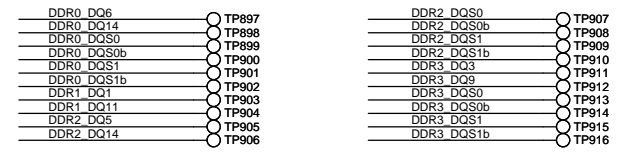


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Document: BCM97405MBv00 Schematic  
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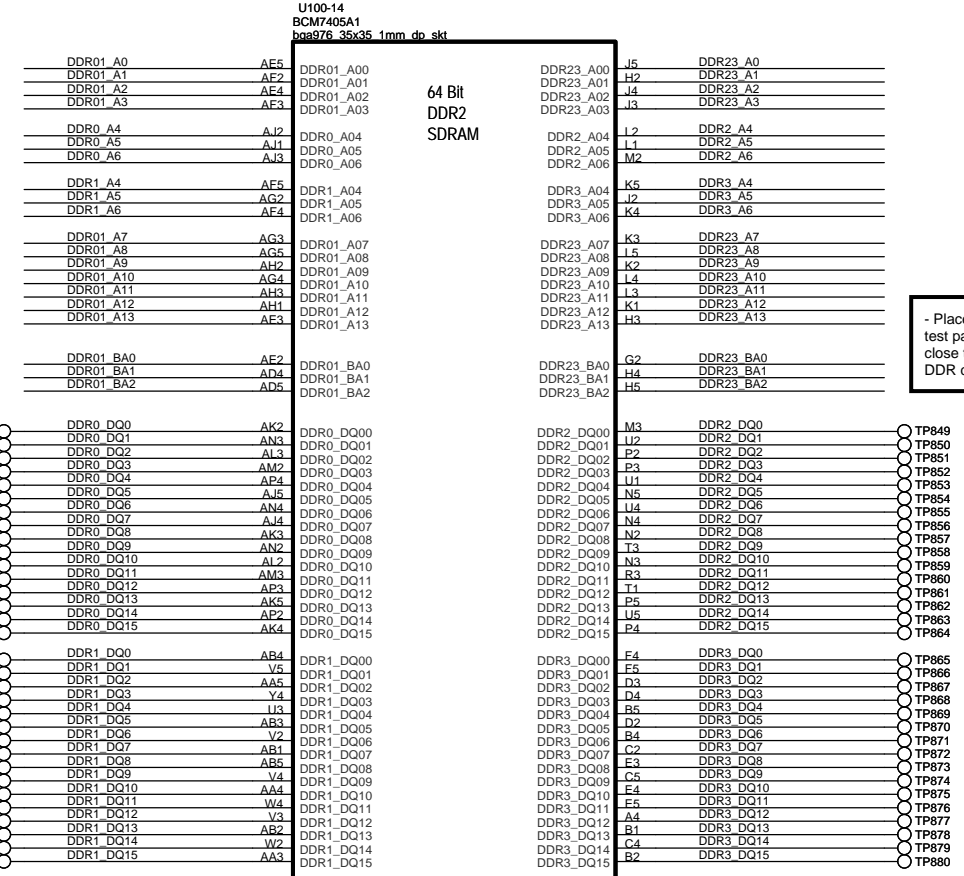


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Document: BCM97405MBv00 Schematic  
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Modified: Friday, February 01, 2008  
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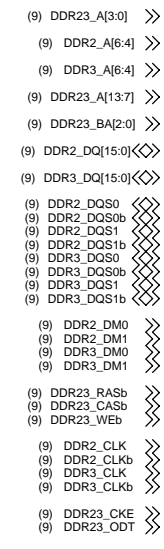
- Place these test pads as close as possible to the Bcm7405 balls/vias where they originate.



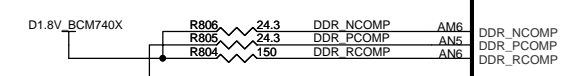
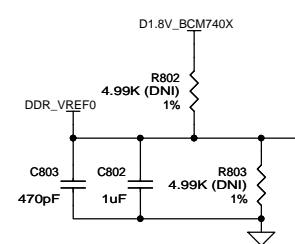
- Place these test pads close to the DDR chips.



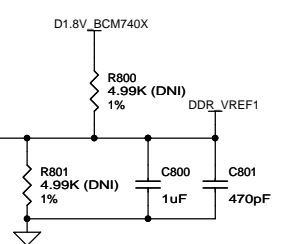
- Place these test pads close to the DDR chips.



- Place these GND test pads close to their corresponding signal test pads for probing.



- Place these GND test pads close to their corresponding signal test pads for probing.



**DDR2 rules for 64-bit interface:**

BCM7405 pads for DQ / DQS / DM can select ODT impedance of 75 or 150 ohms.

**Chip Placement -**

Place two DDR2 chips on the top side and two on the bottom, and tuck the DDR2 chips as close to BCM740X DDR2 interface as possible.

**Trace lengths -**

- CLK / CLKB < 2" total length, delta in each pair < 50 mils = 1.27mm
- CLK0,1,2,3 < 50 mils delta among all clocks
- DQS / DQSB < 1.5" total length, delta in each pair < 50 mils = 1.27mm
- DQ / DQM < 1.5" total length to avoid ISI and crosstalk
- All other as short as possible

- DQS / DQ / DM < 60ps delta within each byte lane for DDR2-800
- Address / Control < 120ps delta with respect to each CLK for DDR2-800
- CLK to DQS < 500 mils for the same DDR device (60ps on FR4 = ap. 360 mils = 9mm)

**Trace Impedances -**

- 60 ohms +/- 10% except as noted
- CLK / CLKB 100 ohms +/- 10% differential, 60 ohms +/- 10% single-ended
- DQS / DQSB 100 ohms +/- 10% differential

**Terminations and Capacitors -**

CLK / CLKB -- Place the pull-up / pull-down termination resistors as close to the DDR memory balls as possible. Avoid creating stubs. Route and terminate all 4 CLK's even if not used.

Address / Control -- Place parallel termination resistors/rpacs at end of daisy chains by SDRAM, or if routes are T's then place at branch of T with stubs < 0.200". Termination resistors may be swapped to improve routing.

VREF0 / VREF1 -- Place voltage divider resistors and associated capacitors close to their corresponding balls on the BCM740X chip. Use high-quality ceramic capacitors.

VREF on SDRAM -- Place high-quality ceramic bypass caps close to their corresponding VREF balls as shown on the next sheet of the schematic.

**Routing -**

DDR\_VREF0 and DDR\_VREF1: Route as 30 mil trace

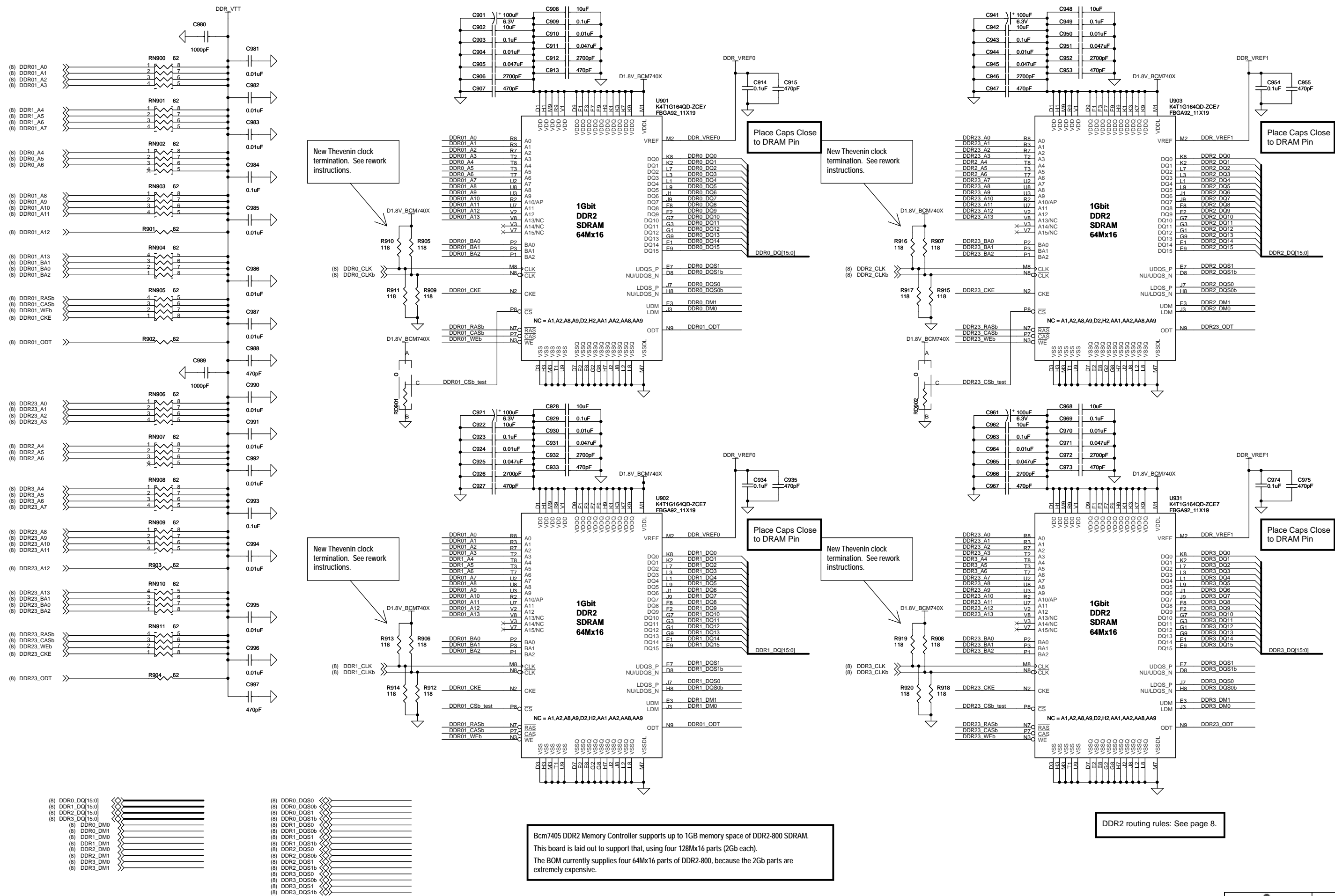
Do not tie DDR\_VREF to DDR\_VTT: It would inject noise onto DDR\_VREF.

NCOMP and PCOMP: Route as 10 mil trace

All traces should have >= 3:2 spacing ratio from the reference GND/PWR layer. (e.g. 7.5 mil line-to-line spacing or more for a 5 mil dielectric thickness) It is best if 3:1 ratio is used for DQS / DQ / DM wherever possible.

JEDEC has defined a common landing pattern (CLP) for use with different package options of DDR2 chips. By using the CLP, a PCB can accommodate all DDR2 device configurations and will be compatible with most package options,

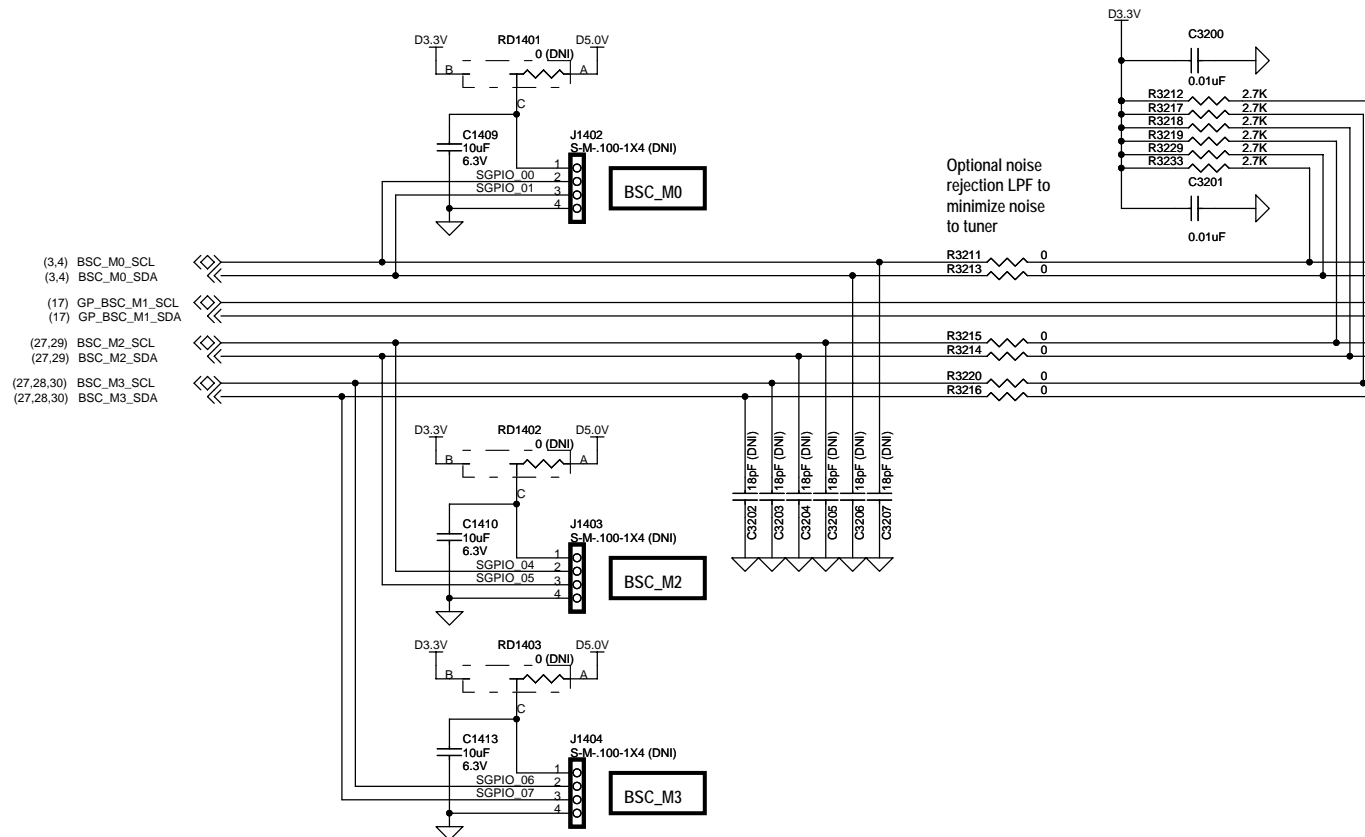
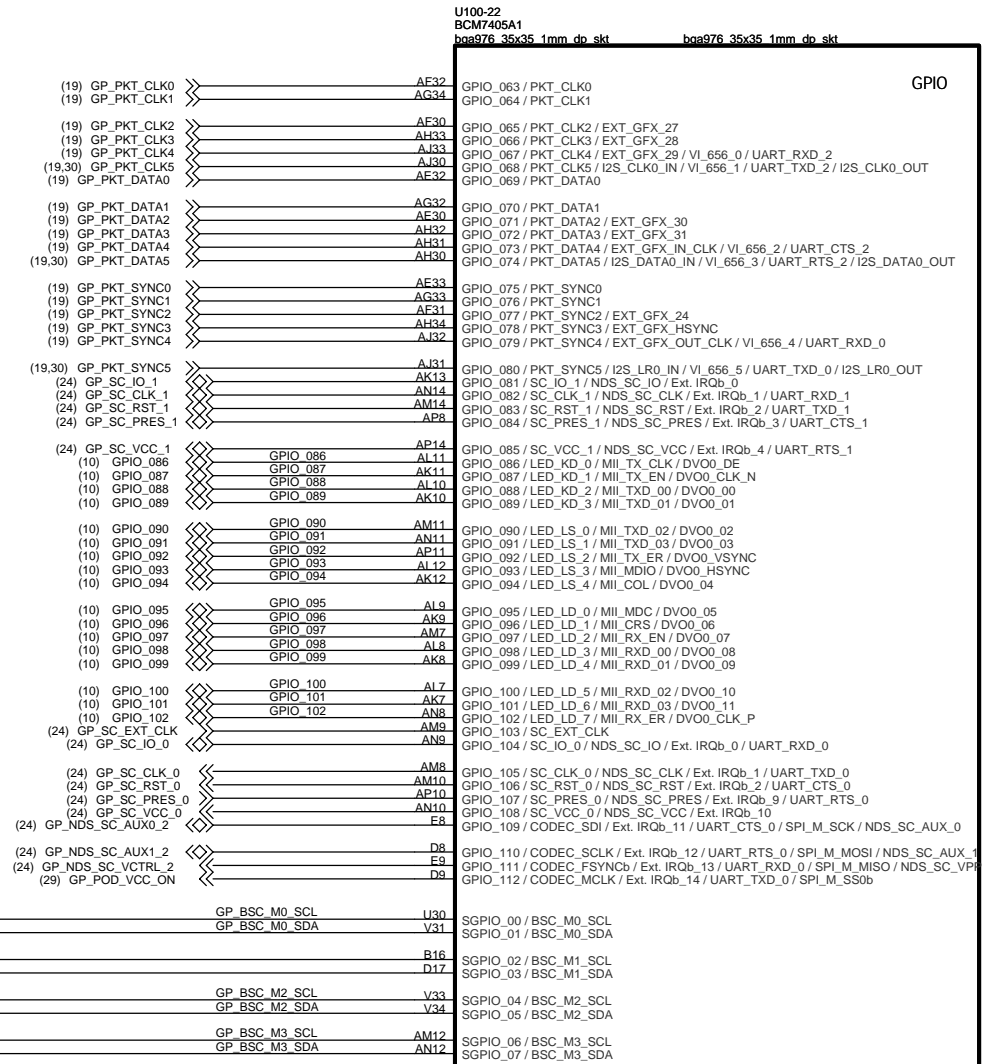
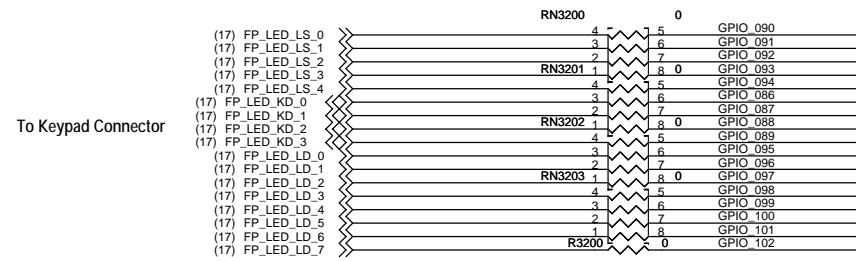
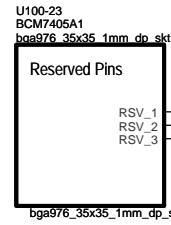




Bcm7405 DDR2 Memory Controller supports up to 1GB memory space of DDR2-800 SDRAM. This board is laid out to support that, using four 128Mx16 parts (2Gb each). The BOM currently supplies four 64Mx16 parts of DDR2-800, because the 2Gb parts are extremely expensive.

DDR2 routing rules: See page 8.





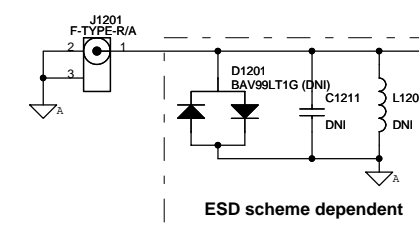
IRQ's used in this design:

- 02 -- ITU-BR 656
- 03 -- POD
- 10 -- Bcm3510
- 11 -- Slot 0A
- 12 -- Slot 0B
- 13 -- Slot 1A
- 14 -- Slot 1B

LNA Center Frequency Options:

Frequency	L1202
433 MHz	1.6 nH
385 MHz	2.7 nH

UHF Receiver Antenna Connector

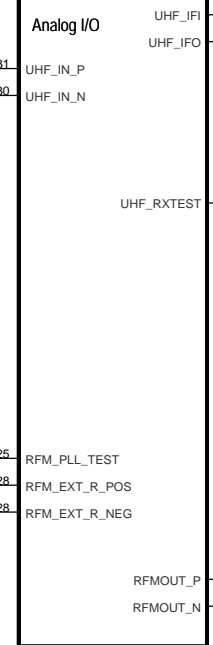


ESD scheme dependent

The LNA area uses a 2-layer PCB, but the long traces from CD1201/CD1202 to BCM740x uses 4-layer. Copy the LNA component pads, floods, and vias exactly the same as the Broadcom's reference layout.

Route as 50 Ohm differential references to layer 2 (7 mils width), separate differential traces by at least 12 mils.

Do NOT connect RFM\_EXT\_R\_NEG to ground.



Route RFM\_DAC\_P and RFM\_DAC\_N as 150 Ohm differential pair, reference to V\_CENTER plane on layer 3.

Place R1229/R1230 near T1202 to minimize the stubs from RFM output.

Place R1228 near R1206 to minimize the stubs from RFM output.

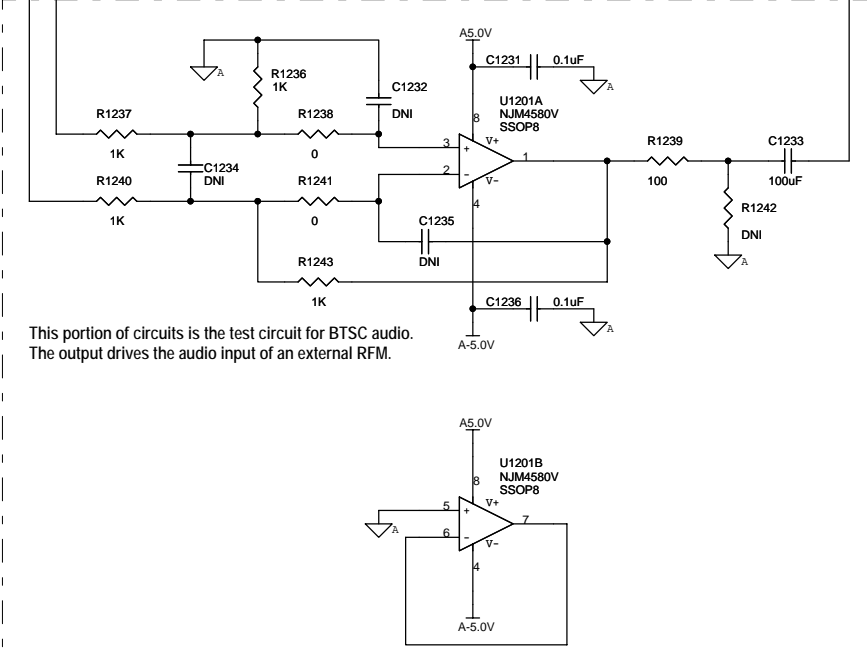
RF Output Level Options:

Approximate RF Output Level	R1208 R1209 (5%)	R1206 (5%)
+40 dBmV	430 Ohm	27 Ohm
+30 dBmV	110 Ohm	180 Ohm
+20 dBmV (Default)	82 Ohm	510 Ohm
+15 dBmV	82 Ohm	1000 Ohm
+10 dBmV	82 Ohm	1800 Ohm
0 dBmV	75 Ohm	5600 Ohm

Use 75 Ohm line all the way to F-connector J1204.

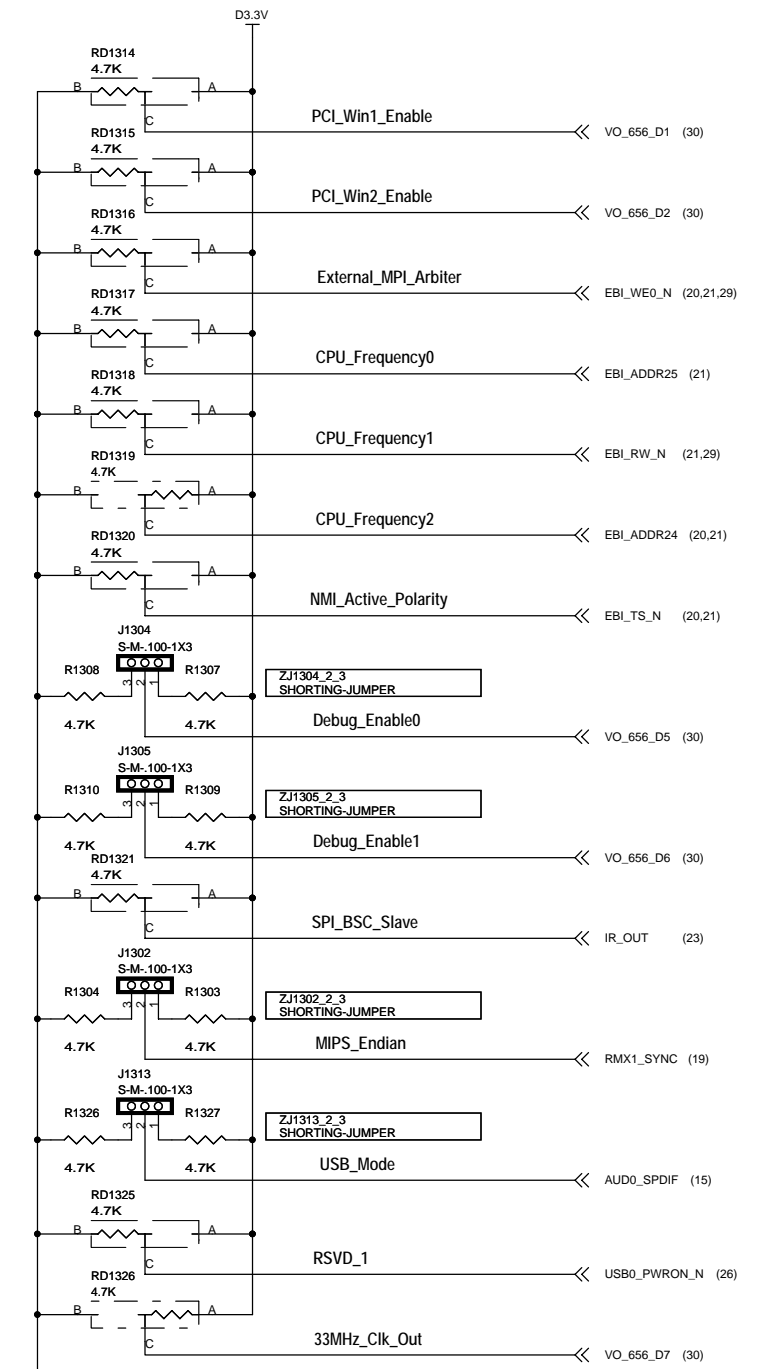
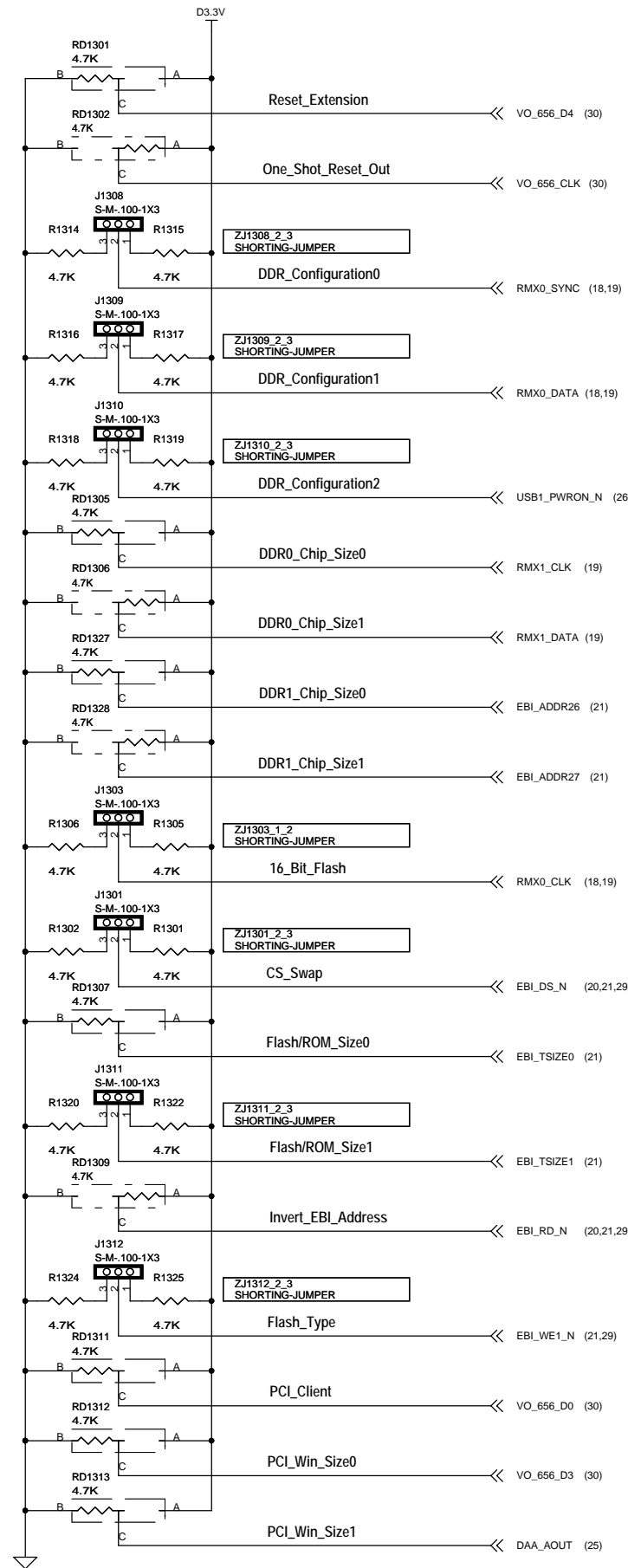
Place all circuits from transformer T1202 to C1209 near F-connector J1204.

This portion of circuits is the test circuit for BTSC audio. The output drives the audio input of an external RFM.

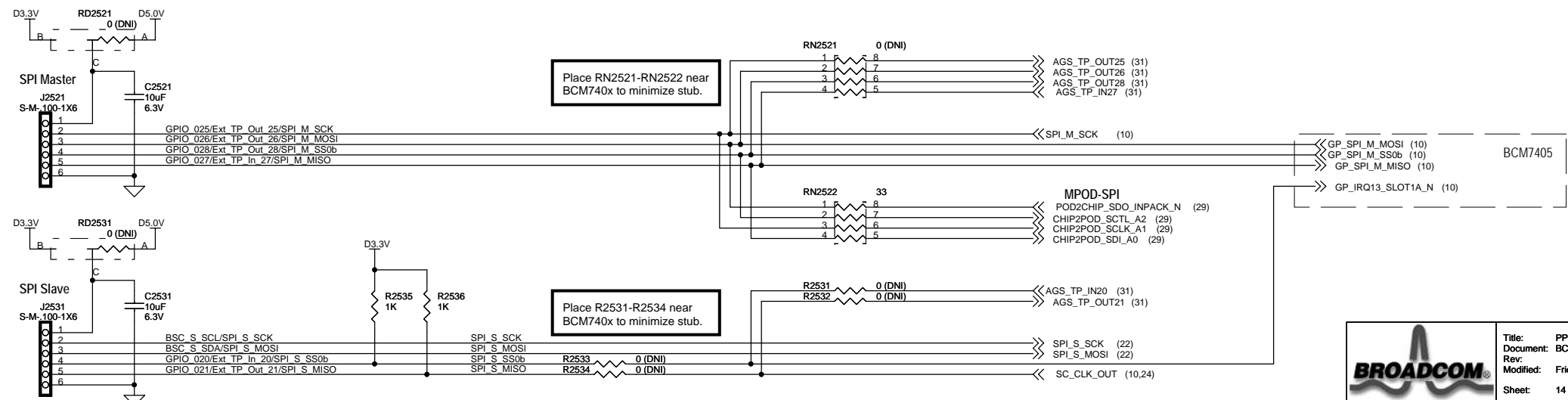
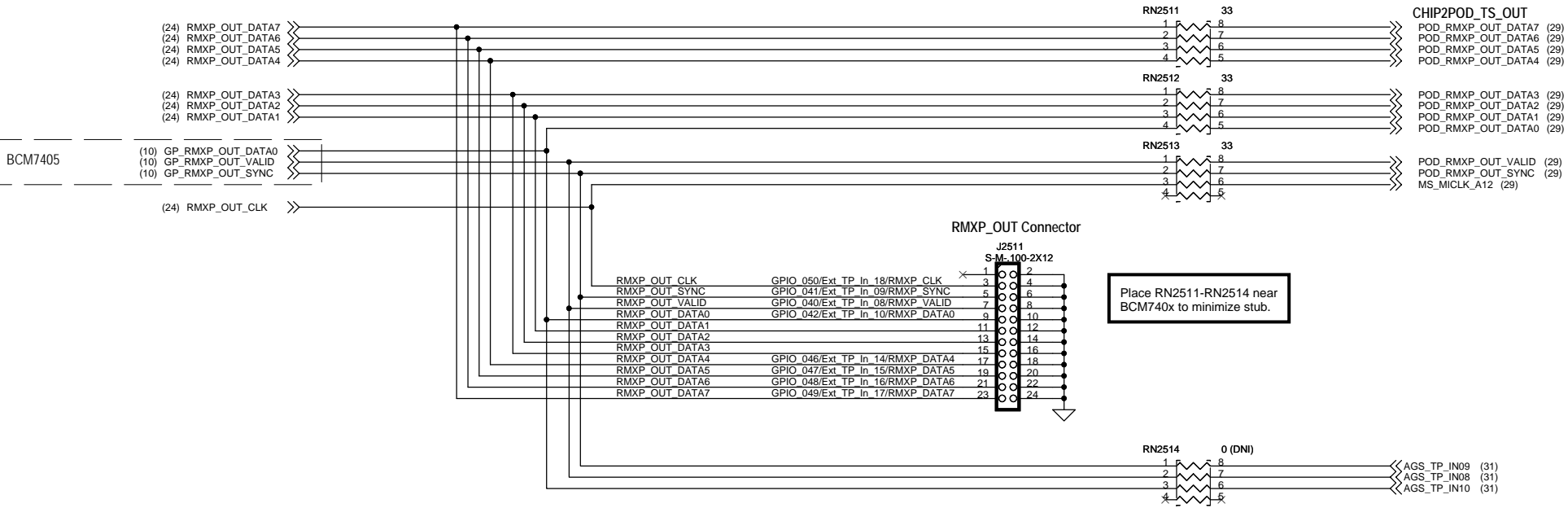
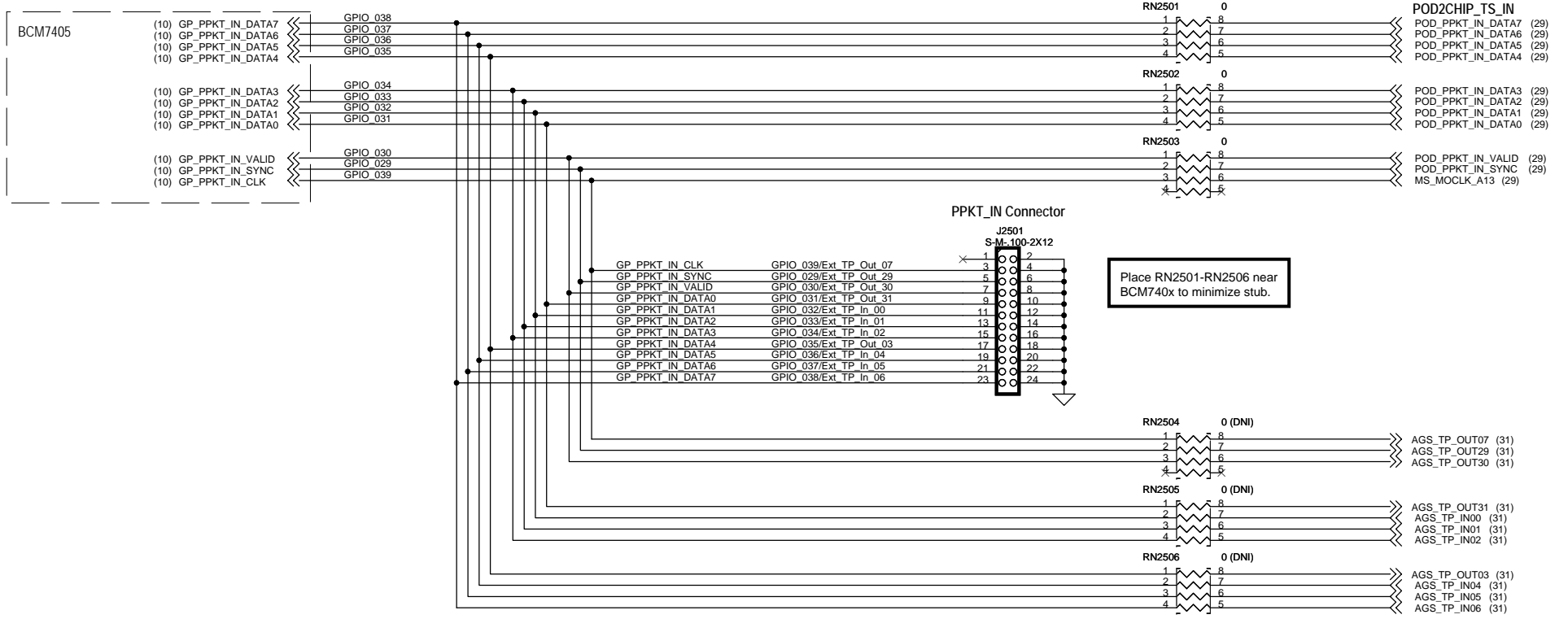


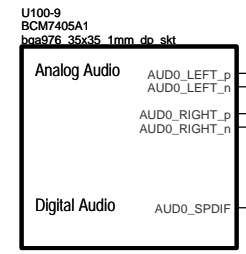
BCM7405Ax Strap Options

Strap Name	Strap Bit	Description	Pin	Default	Comments
Reset_Extension	strap_reset_ext_mode	0: No delay 1: 200 ms (EBI_CS# delayed by 1.6 ms)	VO_656_4	0	
One_Shot_Reset_Out	strap_reset_outb_def_val	0: Level reset output behavior 1: One shot reset output behavior	VO_656_CLK	1	One shot reset output behavior is compatible to BCM3560
DDR_Configuration[2:0]	strap_ddr_config_0 strap_ddr_config_1 strap_ddr_config_2  (LSB is 0, MSB is 2)	000: 64-bit UMA (MEMC0) 001: 32-bit UMA (MEMC0) 010: 16-bit UMA (MEMC0) 100: 32 + 16 Non-UMA (MEMC0:32-bit, MEMC1:16-bit) 101: 16 + 16 Non-UMA (MEMC0:16-bit, MEMC1:16-bit) 110: 16 + 16 Non-UMA (MEMC0:16-bit, MEMC1:16-bit) (LSB is 0, MSB is 2)	RMX_SYNC0 RMX_DATA0 USB1_PWRON	0 0 0	Configuration of 64-bit DDR interface Currently, 32-bit UMA is NOT supported by 7405.
DDR0_Chip_Size[1:0]	strap_ddr0_device_config_0 strap_ddr0_device_config_1	00: 16Mx16 bit devices on MEMC0 01: 32Mx16 bit devices on MEMC0 10: 64Mx16 bit devices on MEMC0 11: 128Mx16 bit devices on MEMC0	RMX_CLK1 RMX_DATA1	0 1	Device configuration of MEMC0
DDR1_Chip_Size[1:0]	strap_ddr1_device_config_0 strap_ddr1_device_config_1	00: 16Mx16 bit device on MEMC1 01: 32Mx16 bit device on MEMC1 10: 64Mx16 bit device on MEMC1 11: 128Mx16 bit device on MEMC1	EBI_ADDR26 EBI_ADDR27	0 1	Device configuration of MEMC1 (32 + 16 bit mode)
16_Bit_Flash	strap_ebi_boot_memory	If strapped for NOR boot: 0: Boot memory is 8-bit device 1: Boot memory is 16-bit device If strapped for NAND boot: 0: NAND Block 0 not WR-protected 1: NAND Block 0 is WR-protected	RMX_CLK0	?	Per system configuration
CS_Swap	strap_ebi_cs_swap	0: No swap 1: Swap CS_0 and CS_1 signals	EBI_DSb	?	Per system configuration
Flash/ROM_Size[1:0]	strap_ebi_rom_size0 strap_ebi_rom_size1	NOR Flash 0: 64 Mbyte ROM 1: 16 Mbyte ROM 2: 8 Mbyte ROM 3: 4 Mbyte ROM (LSB is 0, MSB is 1)  NAND Flash 0: Disable ECC 1: Disable ECC 2: Enable ECC 3: Enable ECC	EBI_TSIZE0b EBI_TSIZE1b	? ?	Per system configuration
Invert_EBI_Address	strap_ebi_invert_addr	0: Do not invert EBI address 1: Invert upper bits of EBI address	EBI_RDb	1	Tom thinks it's more desirable to have the default be "Invert upper bits of EBI address".
Flash_Type	strap_boot_rom_type	0: Boot ROM is NOR Flash 1: Boot ROM is NAND Flash	EBI_WE1b	?	TBD
PCI_Client	strap_pci_client	0: PCI in bridge (master) mode 1: PCI in client (slave) mode	VO_656_0	0	Usually in master mode
PCI_Win_Size[1:0]	strap_pci_memwin_size_0 strap_pci_memwin_size_1	0: 512 Mbyte Window 1: 1 Gbyte Window 2: 128 Mbyte Window 3: 256 Mbyte Window (LSB is 0, MSB is 1)	VO_656_3 DAA_AOUT	?	Per memory configuration
PCI_Win1_Enable	strap_pci_memwin1_en	0: Disable PCI memory window 1 1: Enable PCI memory window 1	VO_656_1	?	Per system configuration
PCI_Win2_Enable	strap_pci_memwin2_en	0: Disable PCI memory window 2 1: Enable PCI memory window 2	VO_656_2	?	Per system configuration
External_MPI_Arbitrator	strap_external_MPI_arbit	0: Use internal MPI arbiter 1: Use external MPI arbiter	EBI_WE0b	0	Per system configuration
CPU_Frequency[2:0]	strap_CPU_freq_0 strap_CPU_freq_1 strap_CPU_freq_2	0: 297 MHz 1: 324 MHz 2: 351 MHz 3: 378 MHz 4: 405 MHz (default) 5: 432 MHz 6: 459 MHz 7: 148.5 MHz (297 divided by 2)	EBI_ADDR25 EBI_RWb EBI_ADDR24	0 0 ?	Per system configuration 3'b010 is the recommended default.
NMI_Active_Polarity	strap_NMI_polarity	0: Low-active interrupt 1: High-active interrupt	EBI_TSb	?	Per system configuration
Debug_Enable[1:0]	strap_test_debug_en_0 strap_test_debug_en_1	0: Debug mode disabled	VO_656_5 VO_656_6	0 0	Internal Debug Port
SPI_BSC_Slave	strap_spi_slave_enable	0: BSC slave port configured 1: SPI slave port configured	IR_OUT	0	Per system configuration - usually in BSC slave
MIPS_Endian	strap_system_big_endian	0: System is LITTLE endian 1: System is BIG endian	RMX_SYNC1	?	Per system configuration
USB_Mode	strap_USB_mode	0: 3rd USB is host mode 1: 3rd USB is client mode	AUD0_SPDIF	0	Per system configuration
RSVD_1	strap_RSVD_1	TBD	USB0_PWRON	0	Per system configuration
33MHz_Clk_Out	strap_33_27_MHz_clock	0: 27 MHz clock output 1: 33 MHz clock output	VO_656_7	1	Per system configuration



Circuits connected to these strapping signals such as EBI, RMX, VO, etc. must not affect the strapping, in some cases, buffers are needed.





I2S audio is found on Sheets 10, 11, 30.

Route as 100 Ohm differential pairs

Put AUD1 GND points as close as possible to connector J1501.

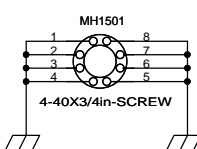
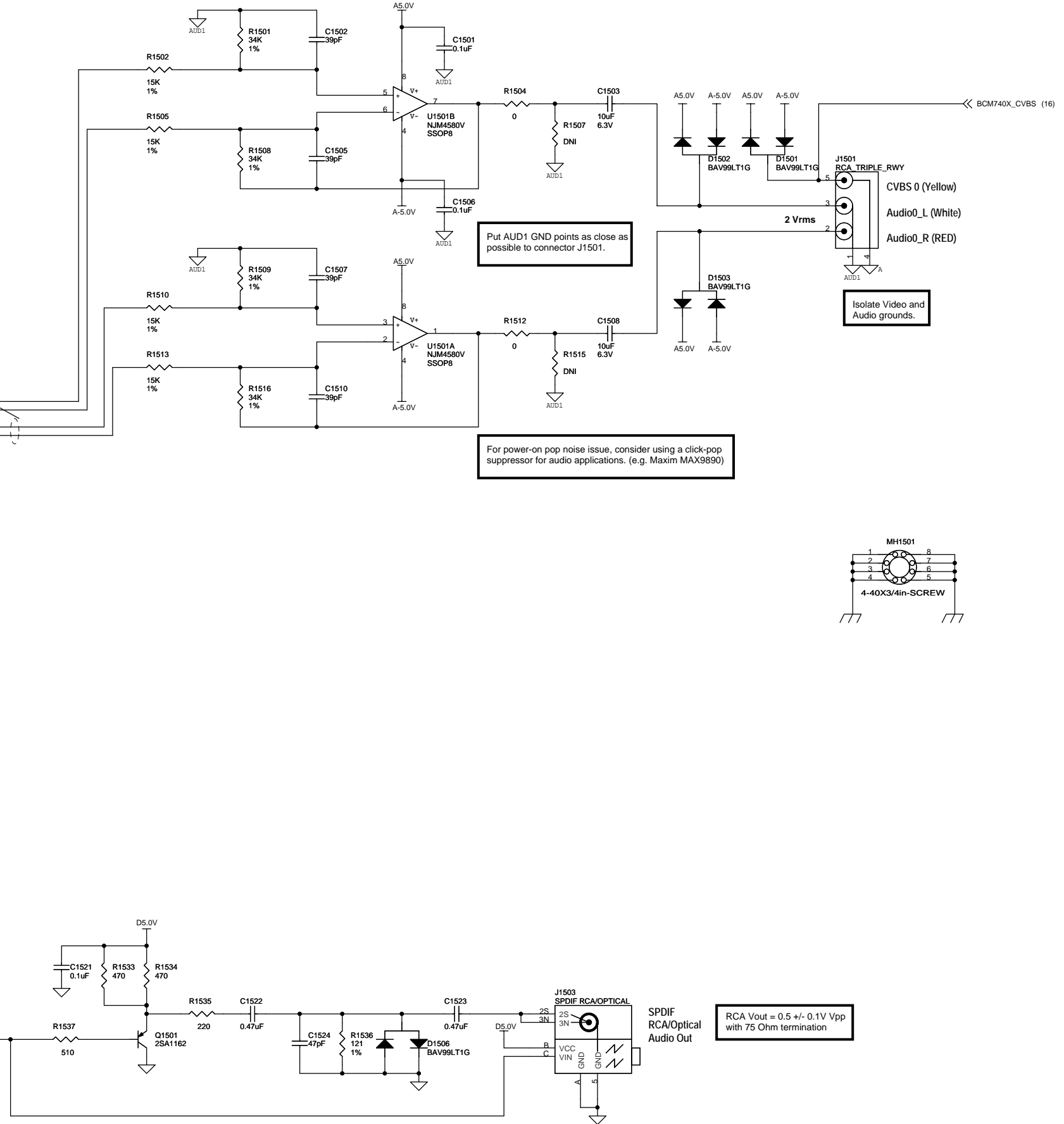
For power-on pop noise issue, consider using a click-pop suppressor for audio applications. (e.g. Maxim MAX9890)

Isolate Video and Audio grounds.

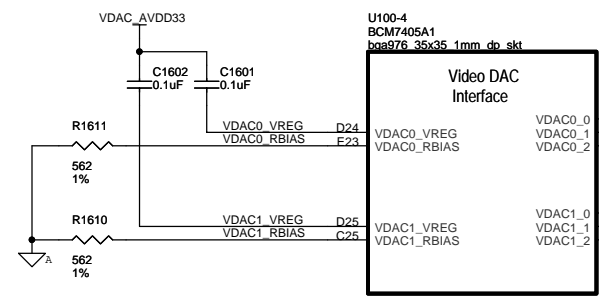
RCA Vout = 0.5 +/- 0.1V Vpp with 75 Ohm termination

Strap Bit  
(13) AUD0\_SPDIF

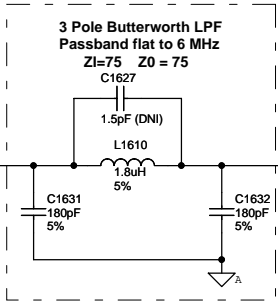
Active LPF/Line Driver  
Fc ~ 130 kHz, Gain = 2



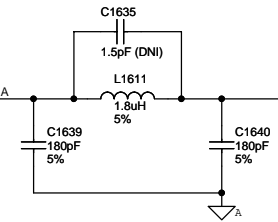
Place bias resistors R1610/R1611 and VDAC voltage regulator capacitors C1601/C1602 near BCM740x and shield them by GND.



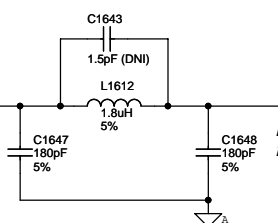
Place 75 ohm terminations <1" from BCM740X



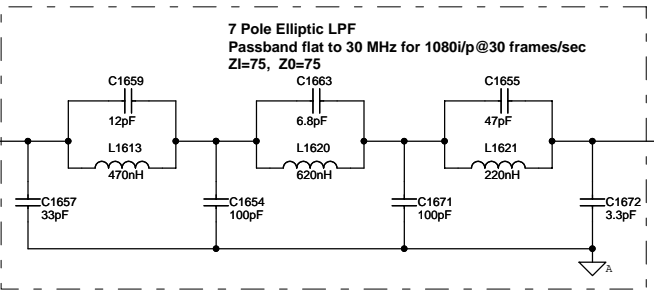
Place inductors so that the fields from adjacent filters DO NOT couple.



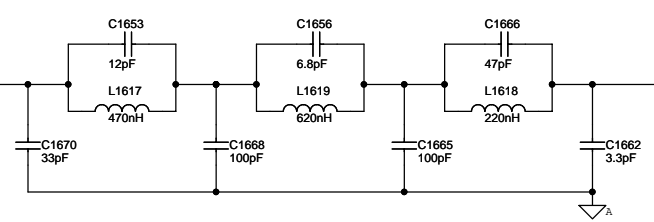
Place inductors so that the fields from adjacent filters DO NOT couple.



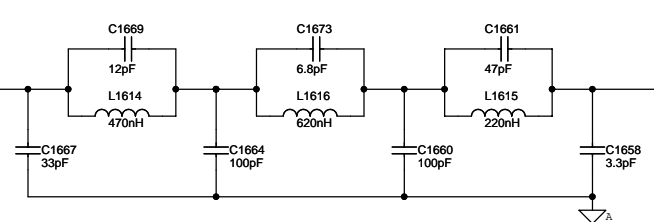
Place inductors so that the fields from adjacent filters DO NOT couple.



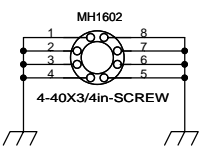
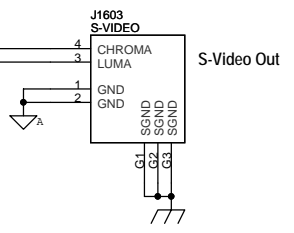
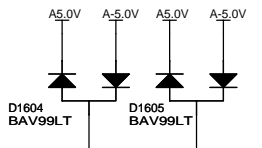
Place inductors & 0 ohm R's so that the fields from adjacent filters DO NOT couple.



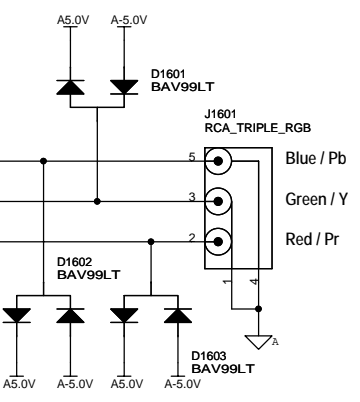
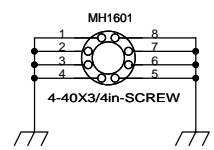
Place inductors & 0 ohm R's so that the fields from adjacent filters DO NOT couple.



Place inductors & 0 ohm R's so that the fields from adjacent filters DO NOT couple.



BCM740X\_CVBS (15)





**HDMI - Layout Guidelines:**

- Differential pairs should be routed on TOP or BOTTOM layers only.
- Trace impedance: 100 ohm differential impedance to the ground plane.
- 5 mils trace width with 7.5 mil air gap on P/N pair.
- Match trace length of differential pairs, 20 mils max within a pair, and 100 mils max between pairs.
- Adjacent TX/RX differential pairs should be separated by more than 50 mils to each other.

Place all ESD diodes as close as possible to J1701

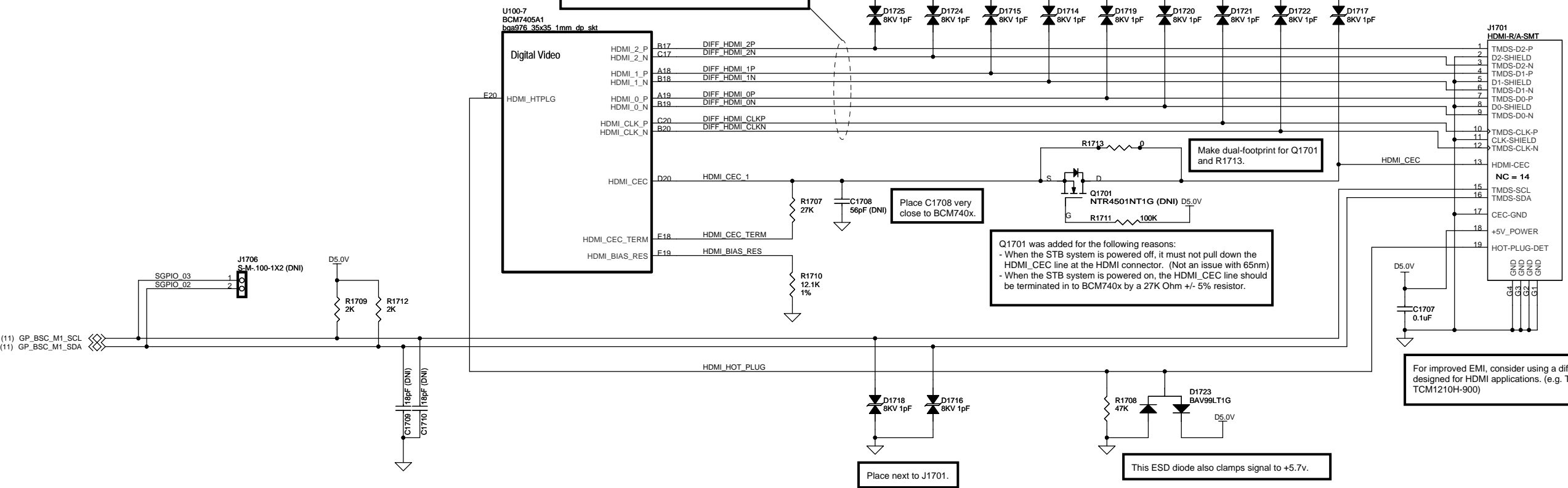
Make dual-footprint for Q1701 and R1713.

Place C1708 very close to BCM740x.

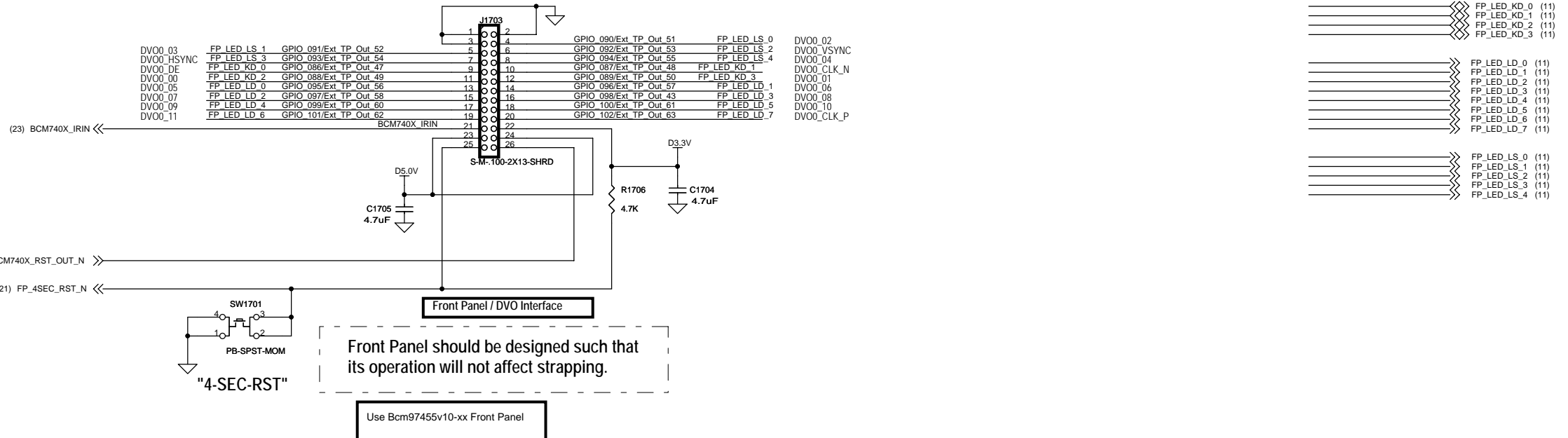
Q1701 was added for the following reasons:  
 - When the STB system is powered off, it must not pull down the HDMI\_CEC line at the HDMI connector. (Not an issue with 65nm)  
 - When the STB system is powered on, the HDMI\_CEC line should be terminated in to BCM740x by a 27K Ohm +/- 5% resistor.

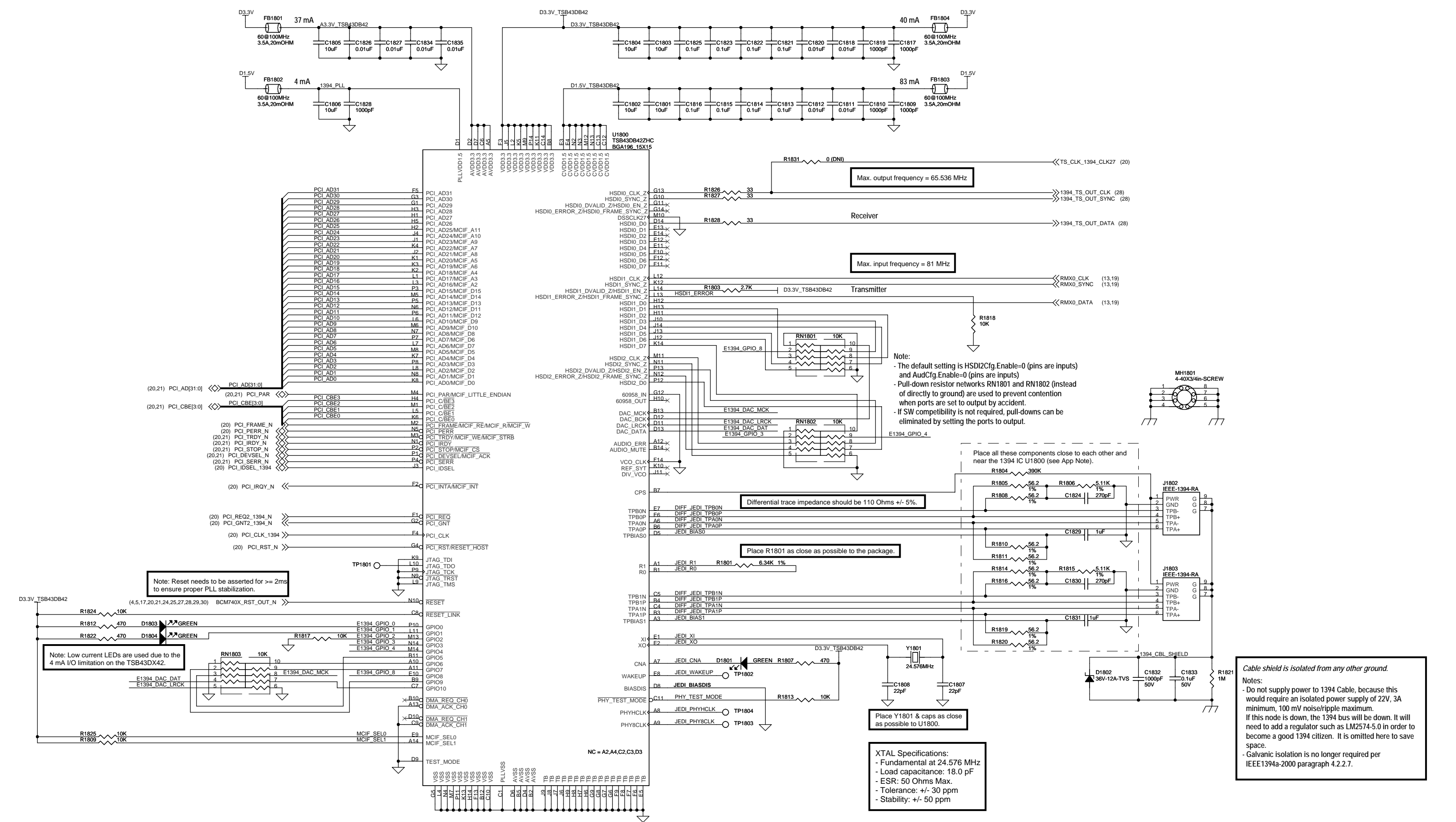
For improved EMI, consider using a differential line filter designed for HDMI applications. (e.g. TDK ACM2012H-900, TCM1210H-900)

DVO signals need to go to Bcm93560DVITX daughter card. Adapter card needed between here and the daughter card.



(11) GP\_BSC\_M1\_SCL  
 (11) GP\_BSC\_M1\_SDA





Note: Reset needs to be asserted for >= 2ms to ensure proper PLL stabilization.

Note: Low current LEDs are used due to the 4 mA I/O limitation on the TSB43DX42.

Differential trace impedance should be 110 Ohms +/- 5%.

Place R1801 as close as possible to the package.

Place Y1801 & caps as close as possible to U1800.

**XTAL Specifications:**  
 - Fundamental at 24.576 MHz  
 - Load capacitance: 18.0 pF  
 - ESR: 50 Ohms Max.  
 - Tolerance: +/- 30 ppm  
 - Stability: +/- 50 ppm

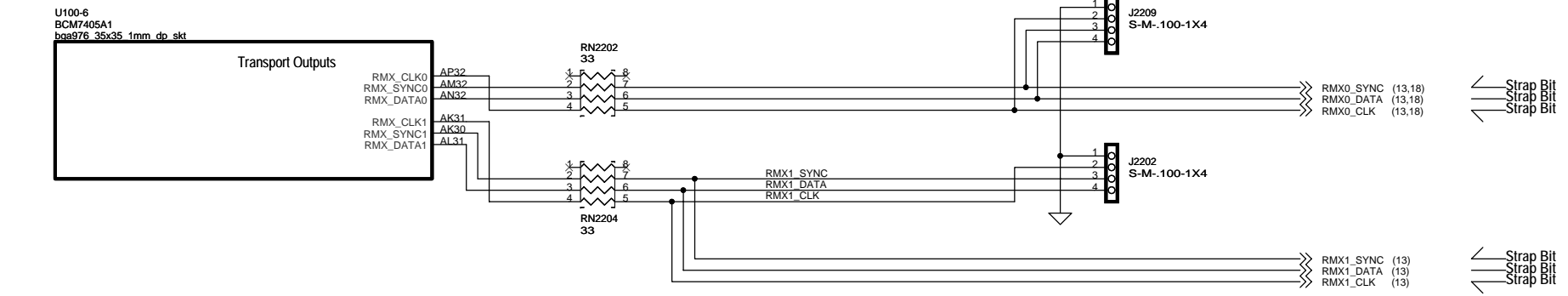
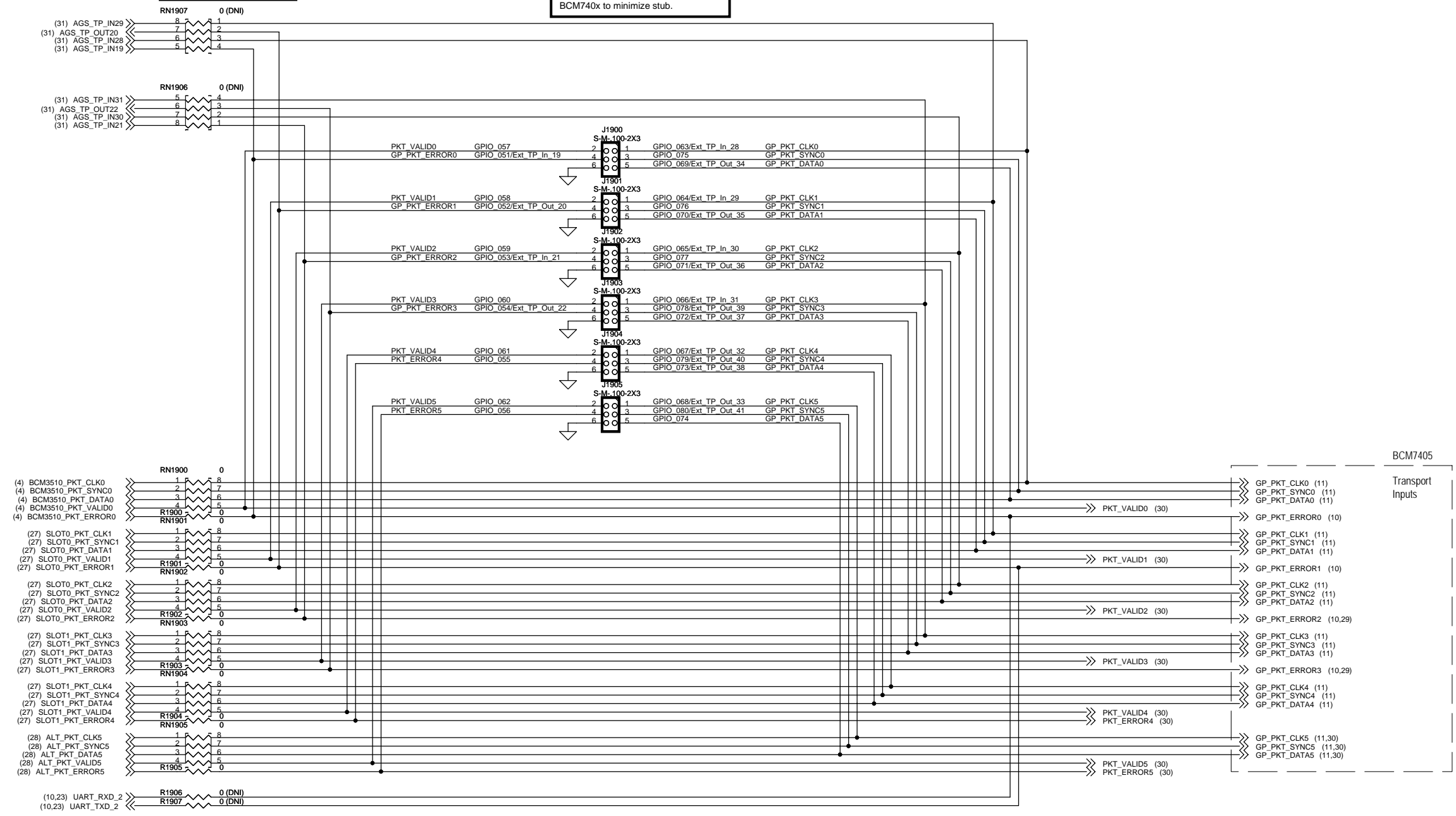
**Note:**  
 - The default setting is HSDI2Cfg.Enable=0 (pins are inputs) and AudCfg.Enable=0 (pins are inputs)  
 - Pull-down resistor networks RN1801 and RN1802 (instead of directly to ground) are used to prevent contention when ports are set to output by accident.  
 - If SW compatiblity is not required, pull-downs can be eliminated by setting the ports to output.

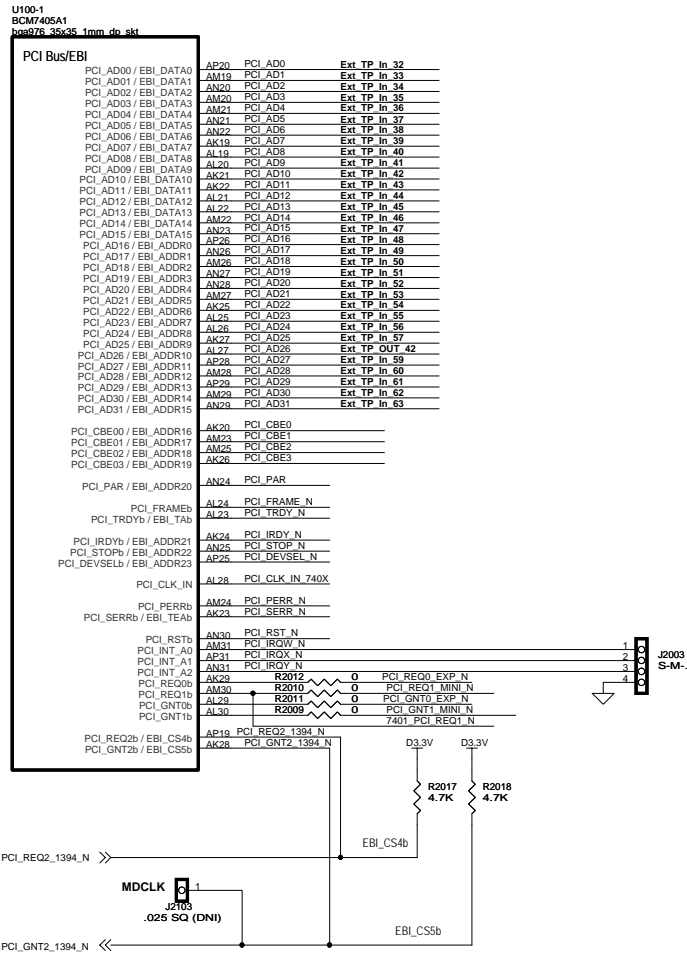
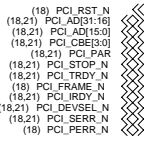
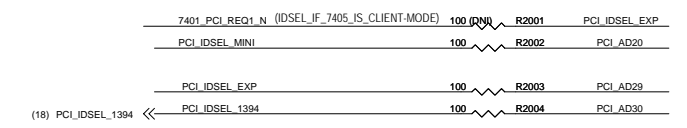
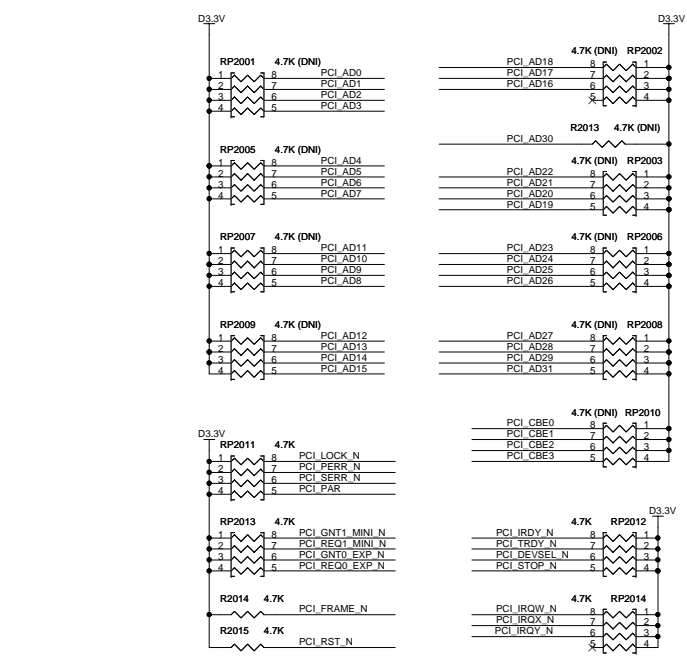
Place all these components close to each other and near the 1394 IC U1800 (see App Note).

**Cable shield is isolated from any other ground.**  
**Notes:**  
 - Do not supply power to 1394 Cable, because this would require an isolated power supply of 22V, 3A minimum, 100 mV noise/ripple maximum.  
 - If this node is down, the 1394 bus will be down. It will need to add a regulator such as LM2574-5.0 in order to become a good 1394 citizen. It is omitted here to save space.  
 - Galvanic isolation is no longer required per IEEE1394a-2000 paragraph 4.2.2.7.

Place R's and RN's near BCM740x to minimize stub.

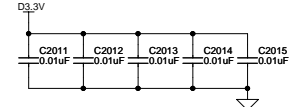
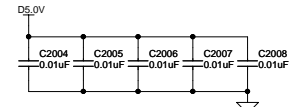
Place test headers J1900-J1905 near BCM740x to minimize stub.



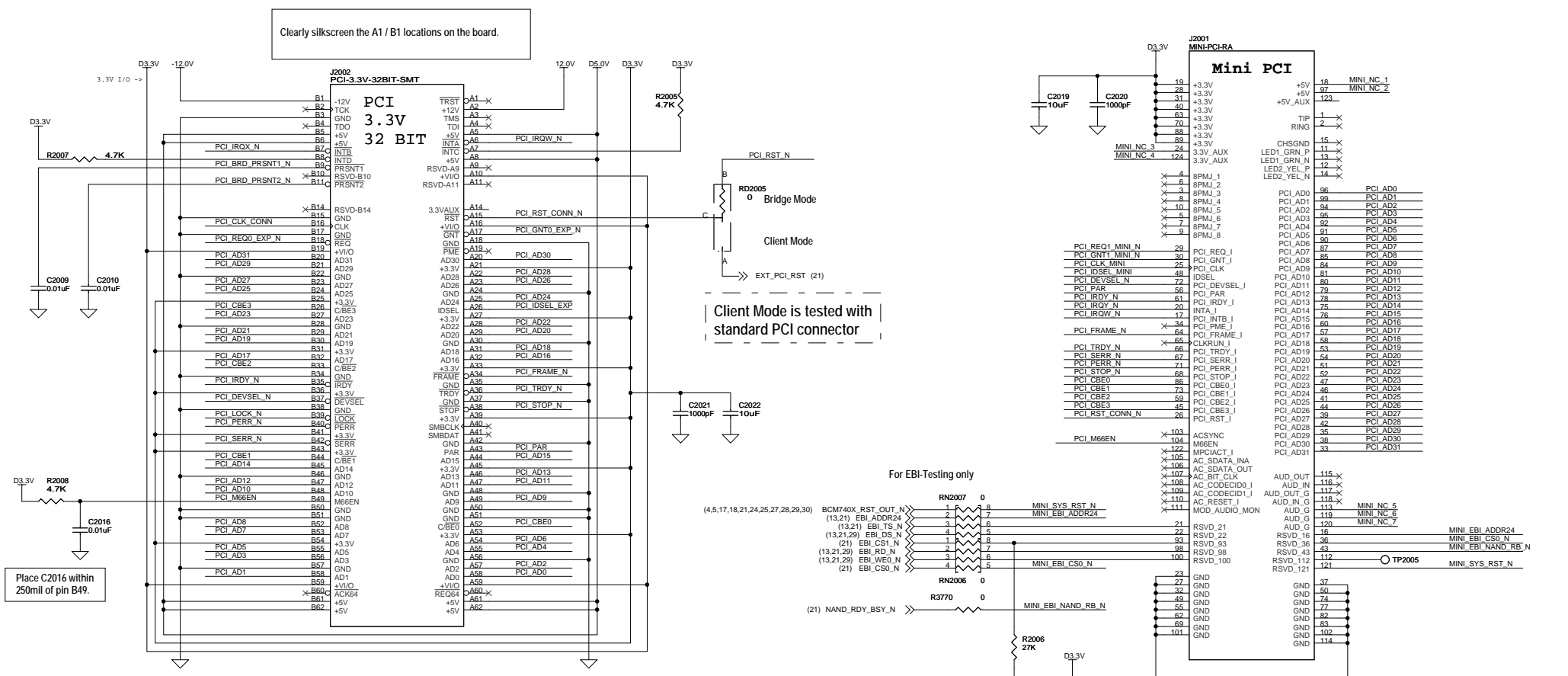


Use PCI\_REQ2 / PCI\_GNT2 for 1394 to be software compatible with Bcm97038.

Place one of each of these capacitors within 250mil to the VI/O pins: B19, B59, A59, A16, and A10



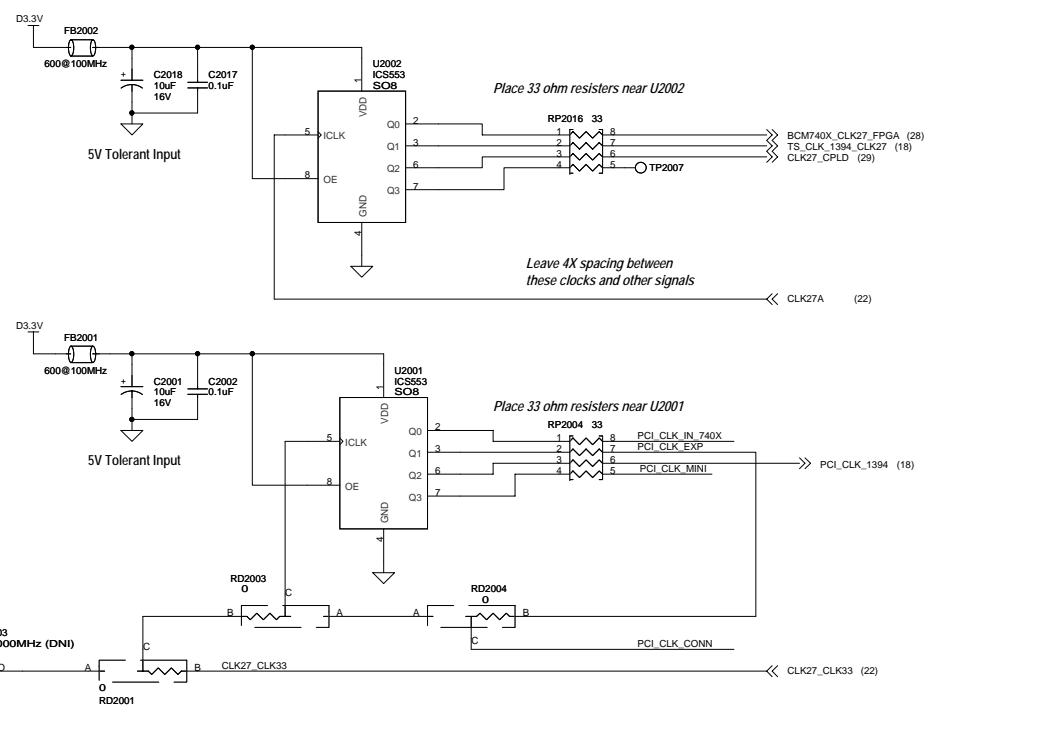
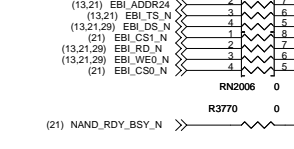
Place C2016 within 250mil of pin B49.

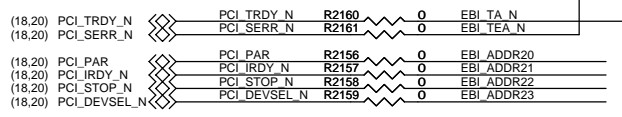
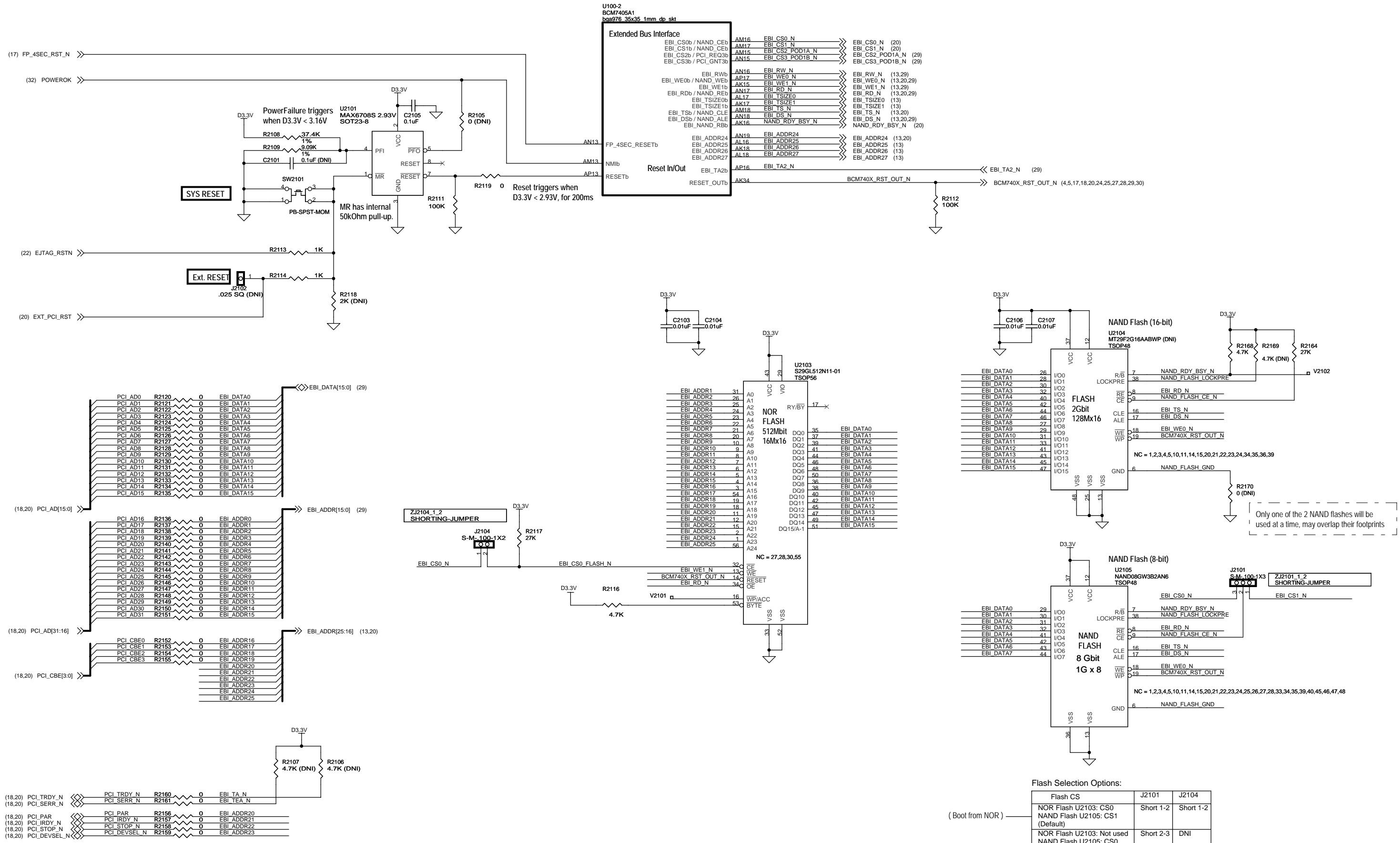


Clearly silkscreen the A1 / B1 locations on the board.

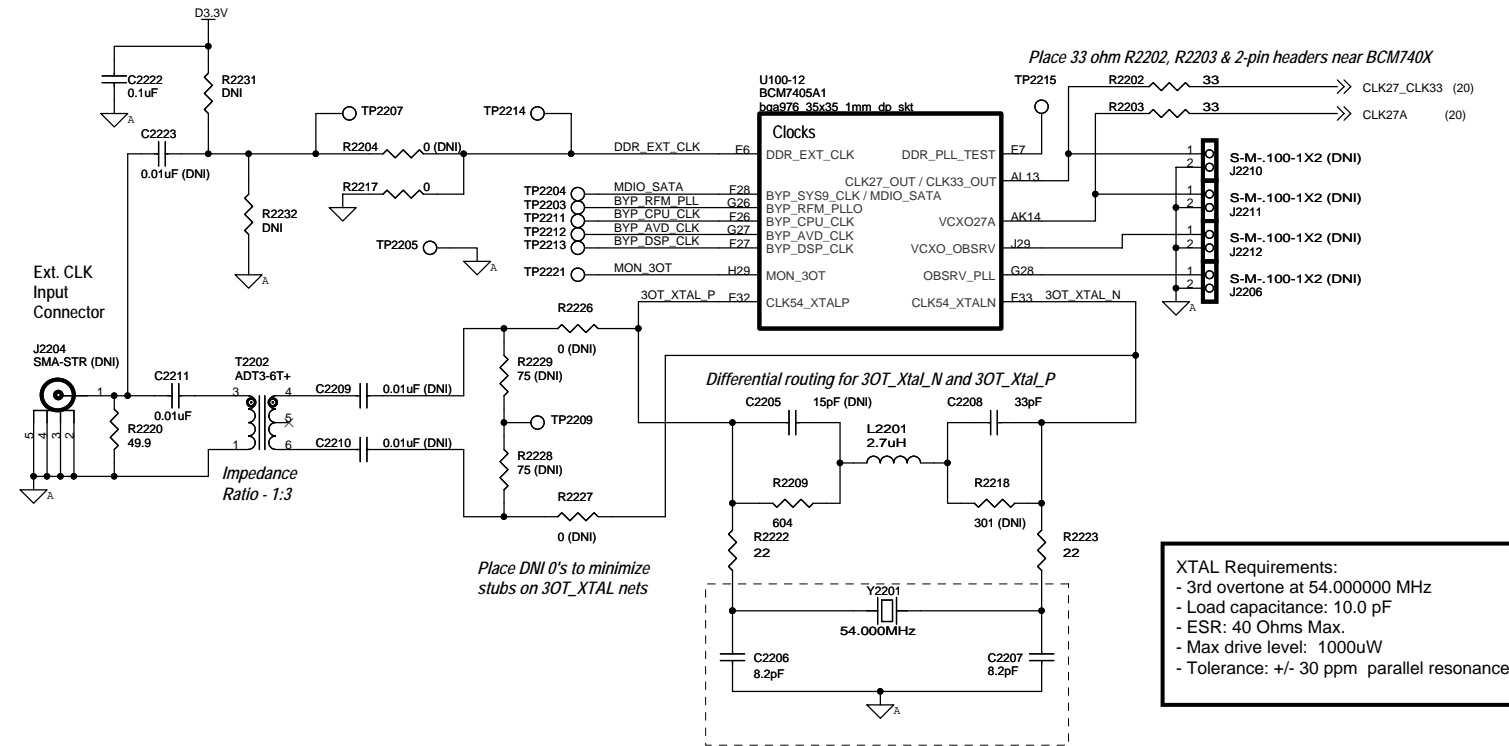
Client Mode is tested with standard PCI connector

For EBI-Testing only





Only one of the 2 NAND flashes will be used at a time, may overlap their footprints



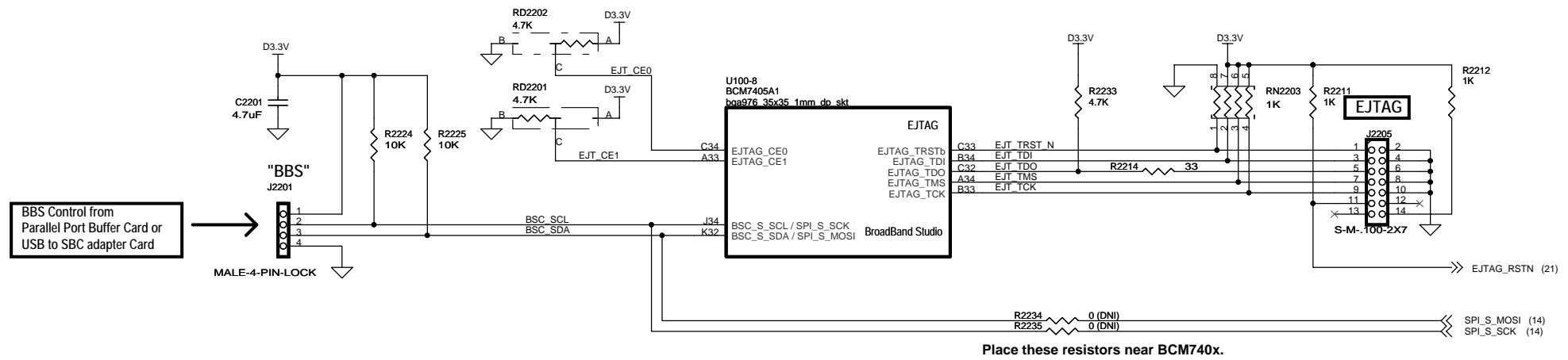
Place 33 ohm R2202, R2203 & 2-pin headers near BCM740X

Place DNI 0's to minimize stubs on 30T\_XTAL nets

**XTAL Requirements:**  
 - 3rd overtone at 54.000000 MHz  
 - Load capacitance: 10.0 pF  
 - ESR: 40 Ohms Max.  
 - Max drive level: 1000uW  
 - Tolerance: +/- 30 ppm parallel resonance

Stitch GND around XTAL and caps inside GND layer cutout. Try to use layout guidelines from 30T application note and keep crystal < 1" from BCM740X.

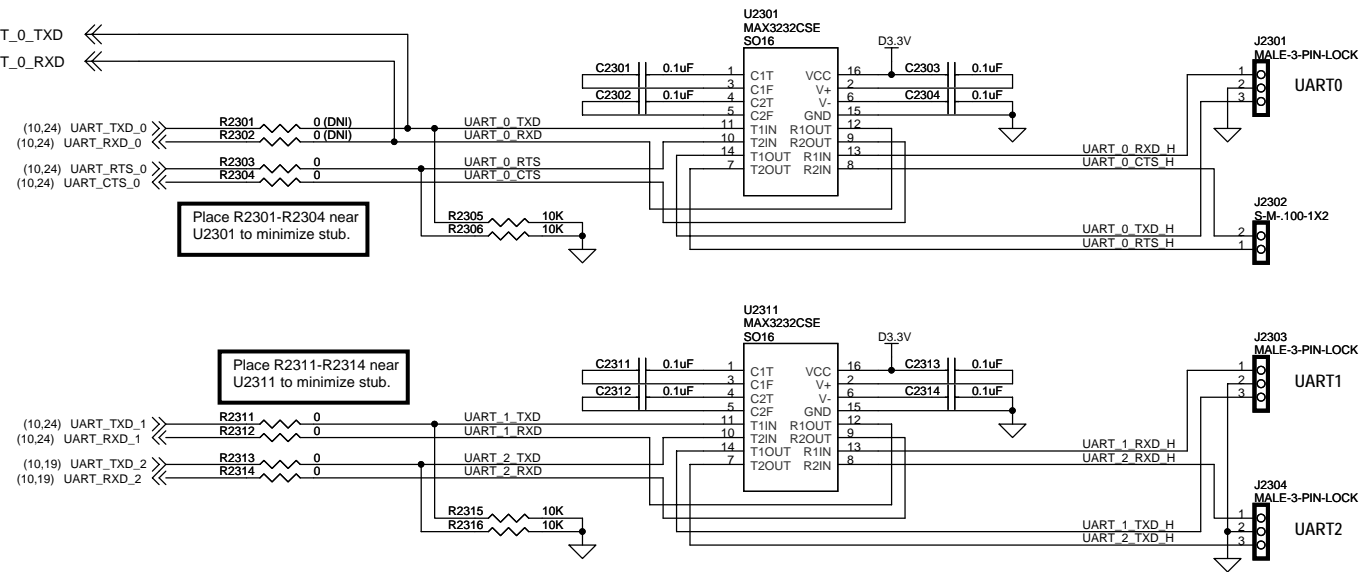
Function	EJTAG_CE0	EJTAG_CE1
Normal EJTAG Operation	1	0
Internal test only	X	1
JTAG boundary scan	0	0



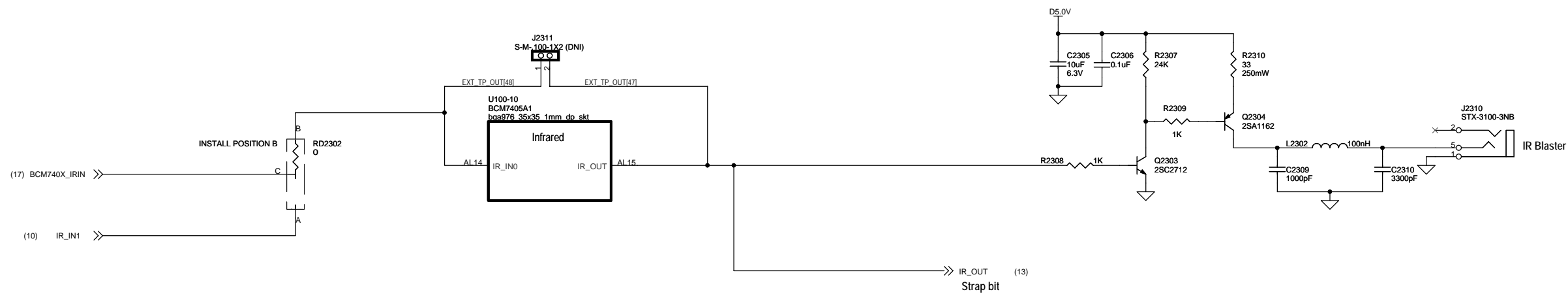
Place these resistors near BCM740x.

The BCM97405 reference board only uses the 2-wire UART ports (no flow control). A 4-wire option (with flow control) is available on UART0 with J2302.

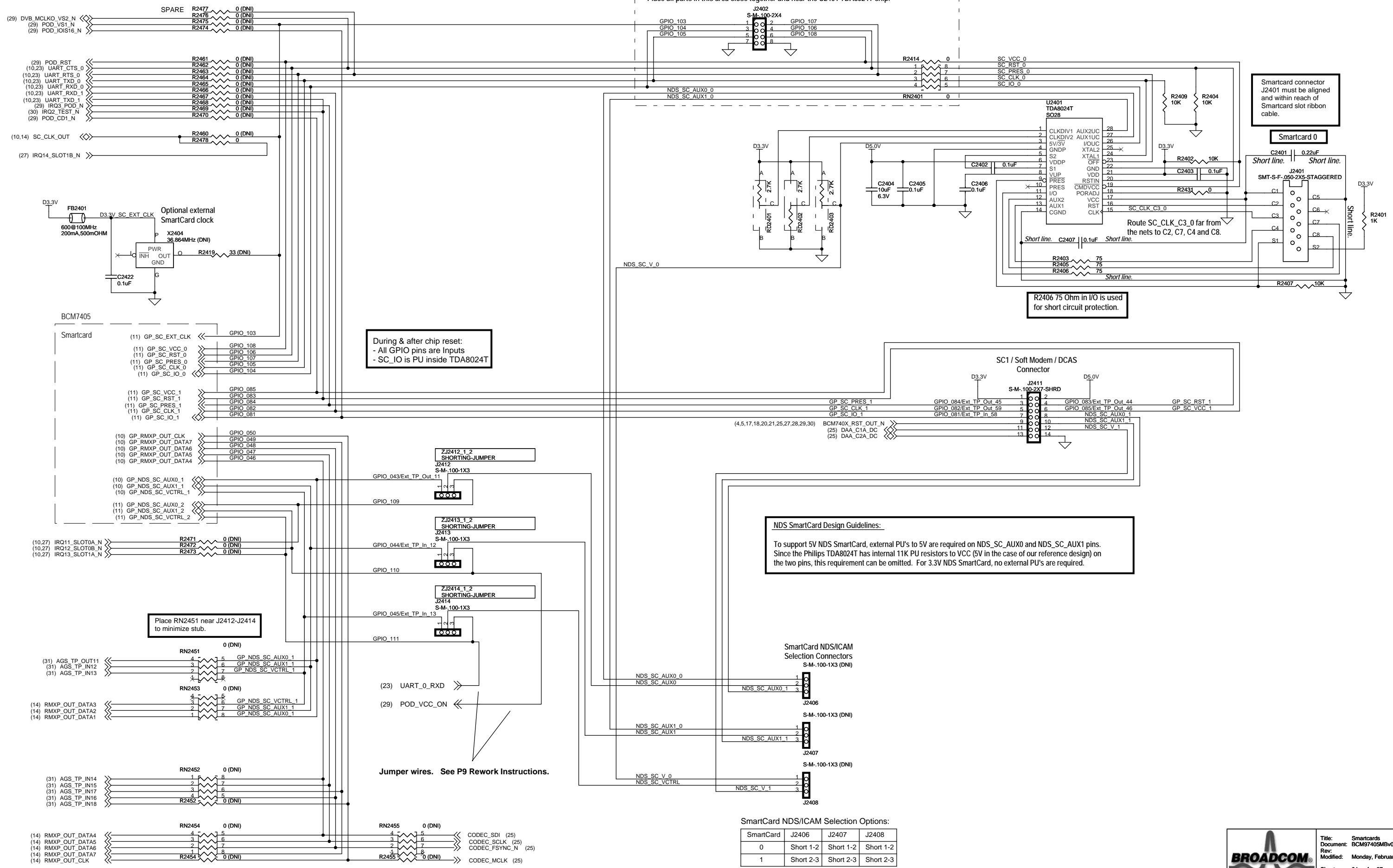
Jumper wires. See P9 Rework Instructions.



The UARTs connect to two sets of GPIO pins on the Bcm7405. One set has MII as another function. If MII is used, then use other set, which has Smart Card 0/1, PKT\_ERROR0/1 as another function.



Place all parts in this area close together and near the U2401 TDA8024T chip.



During & after chip reset:  
 - All GPIO pins are Inputs  
 - SC\_IO is PU inside TDA8024T

R2406 75 Ohm in I/O is used for short circuit protection.

**NDS SmartCard Design Guidelines:**  
 To support 5V NDS SmartCard, external PU's to 5V are required on NDS\_SC\_AUX0 and NDS\_SC\_AUX1 pins. Since the Philips TDA8024T has internal 11K PU resistors to VCC (5V in the case of our reference design) on the two pins, this requirement can be omitted. For 3.3V NDS SmartCard, no external PU's are required.

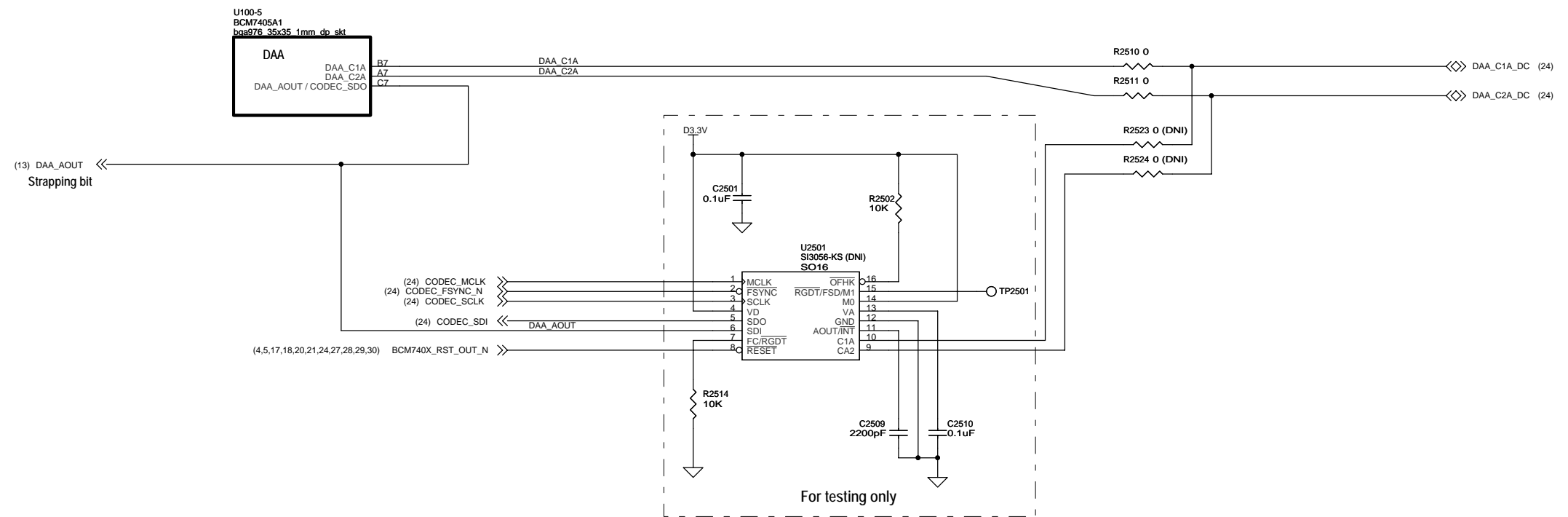
Place RN2451 near J2412-J2414 to minimize stub.

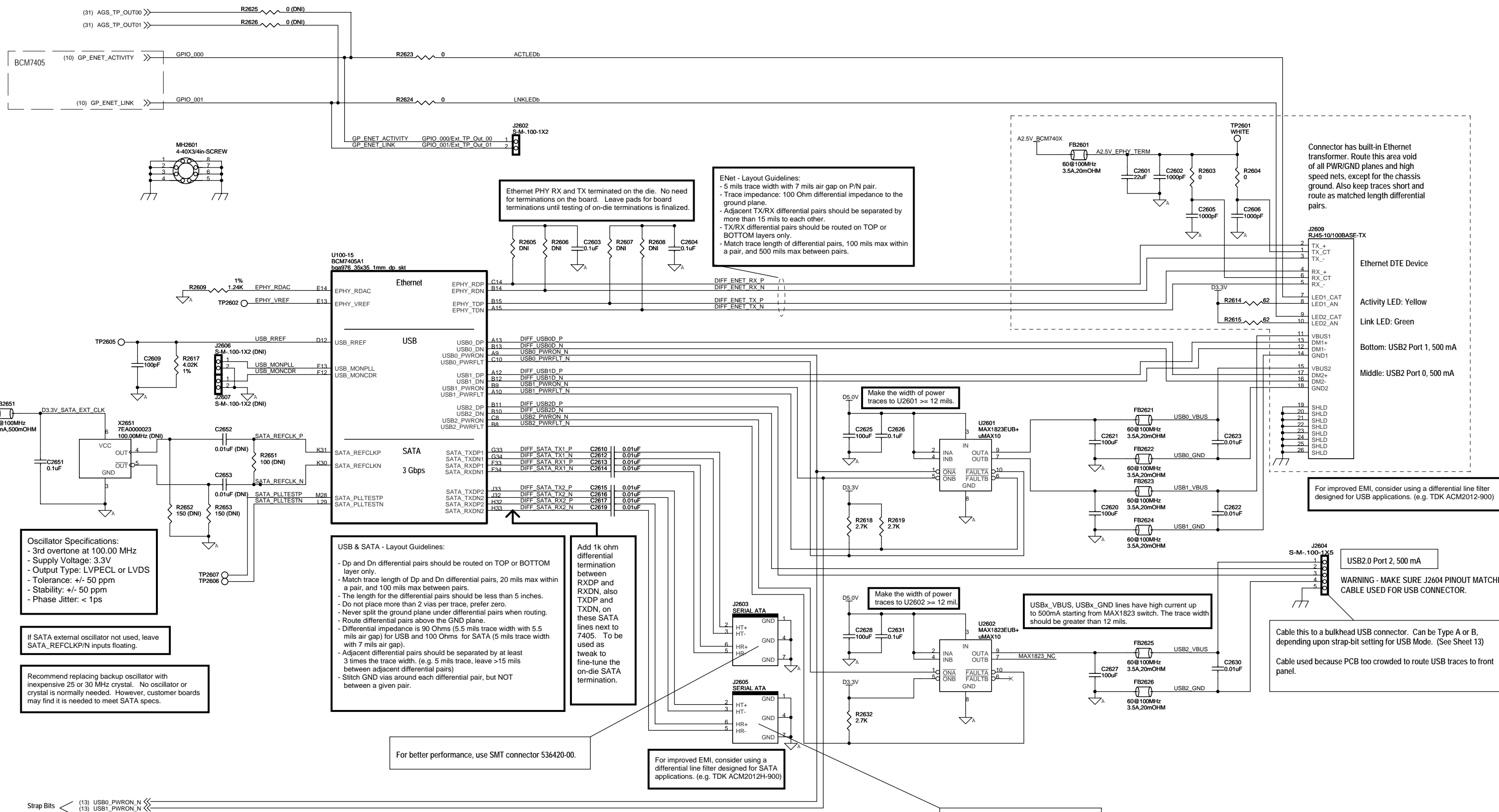
Jumper wires. See P9 Rework Instructions.

SmartCard NDS/ICAM Selection Options:

SmartCard	J2406	J2407	J2408
0	Short 1-2	Short 1-2	Short 1-2
1	Short 2-3	Short 2-3	Short 2-3







**Ethernet - Layout Guidelines:**

- 5 mils trace width with 7 mils air gap on P/N pair.
- Trace impedance: 100 Ohm differential impedance to the ground plane.
- Adjacent TX/RX differential pairs should be separated by more than 15 mils to each other.
- TX/RX differential pairs should be routed on TOP or BOTTOM layers only.
- Match trace length of differential pairs, 100 mils max within a pair, and 500 mils max between pairs.

**Ethernet PHY RX and TX terminated on the die. No need for terminations on the board. Leave pads for board terminations until testing of on-die terminations is finalized.**

**USB & SATA - Layout Guidelines:**

- Dp and Dn differential pairs should be routed on TOP or BOTTOM layer only.
- Match trace length of Dp and Dn differential pairs, 20 mils max within a pair, and 100 mils max between pairs.
- The length for the differential pairs should be less than 5 inches.
- Do not place more than 2 vias per trace, prefer zero.
- Never split the ground plane under differential pairs when routing.
- Route differential pairs above the GND plane.
- Differential impedance is 90 Ohms (5.5 mils trace width with 5.5 mils air gap) for USB and 100 Ohms for SATA (5 mils trace width with 7 mils air gap).
- Adjacent differential pairs should be separated by at least 3 times the trace width. (e.g. 5 mils trace, leave >15 mils between adjacent differential pairs)
- Stitch GND vias around each differential pair, but NOT between a given pair.

**Add 1k ohm differential termination between RXDP and RXDN, also TXDP and TXDN, on these SATA lines next to 7405. To be used as tweak to fine-tune the on-die SATA termination.**

**For better performance, use SMT connector 536420-00.**

**For improved EMI, consider using a differential line filter designed for SATA applications. (e.g. TDK ACM2012H-900)**

**Advise ESD protection on lines going to eSATA connector.**

**Cable this to bulkhead eSATA connector.**

**Connector has built-in Ethernet transformer. Route this area void of all PWR/GND planes and high speed nets, except for the chassis ground. Also keep traces short and route as matched length differential pairs.**

**Ethernet DTE Device**

- Activity LED: Yellow
- Link LED: Green
- Bottom: USB2 Port 1, 500 mA
- Middle: USB2 Port 0, 500 mA

**For improved EMI, consider using a differential line filter designed for USB applications. (e.g. TDK ACM2012-900)**

**WARNING - MAKE SURE J2604 PINOUT MATCHES CABLE USED FOR USB CONNECTOR.**

**Cable this to a bulkhead USB connector. Can be Type A or B, depending upon strap-bit setting for USB Mode. (See Sheet 13)**

**Cable used because PCB too crowded to route USB traces to front panel.**

**Oscillator Specifications:**

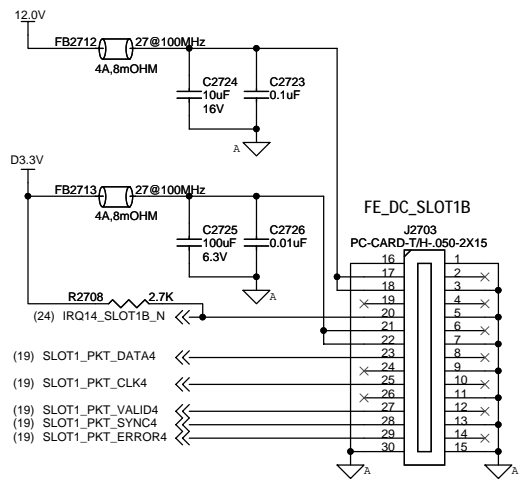
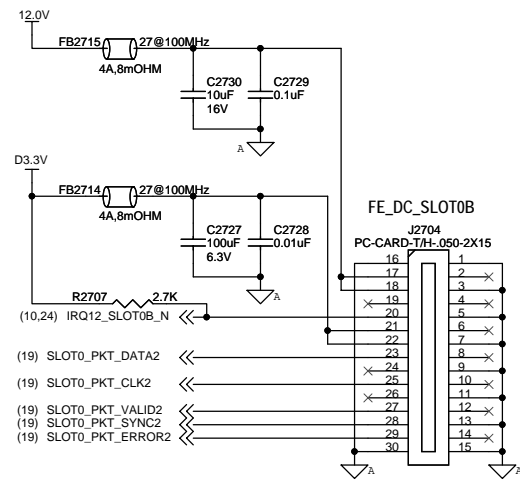
- 3rd overtone at 100.00 MHz
- Supply Voltage: 3.3V
- Output Type: LVPECL or LVDS
- Tolerance: +/- 50 ppm
- Stability: +/- 50 ppm
- Phase Jitter: < 1ps

**If SATA external oscillator not used, leave SATA\_REFCLKP/N inputs floating.**

**Recommend replacing backup oscillator with inexpensive 25 or 30 MHz crystal. No oscillator or crystal is normally needed. However, customer boards may find it is needed to meet SATA specs.**

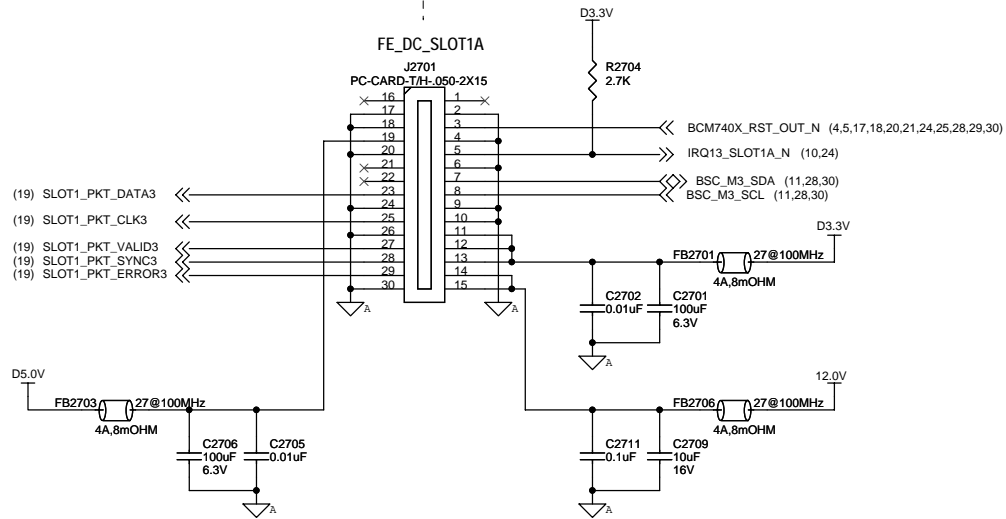
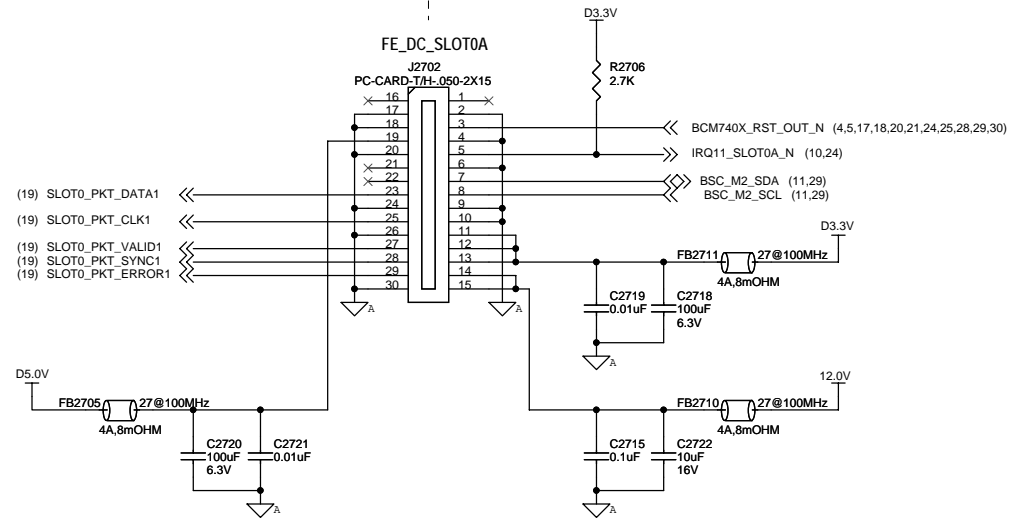
**Strap Bits**

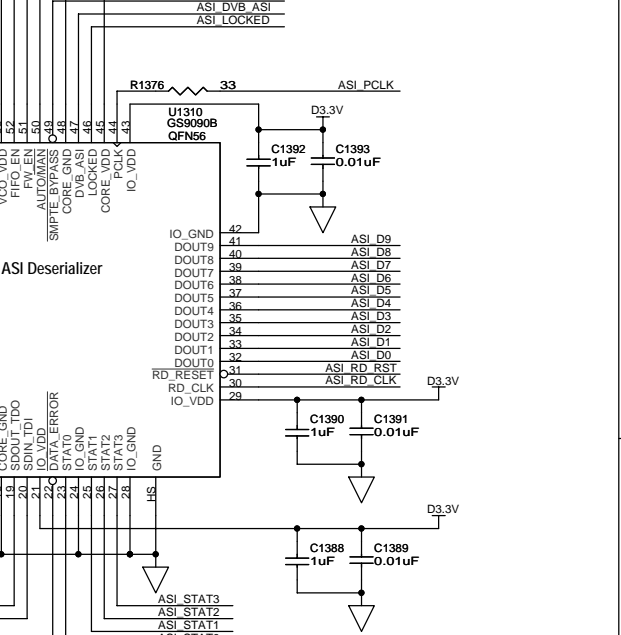
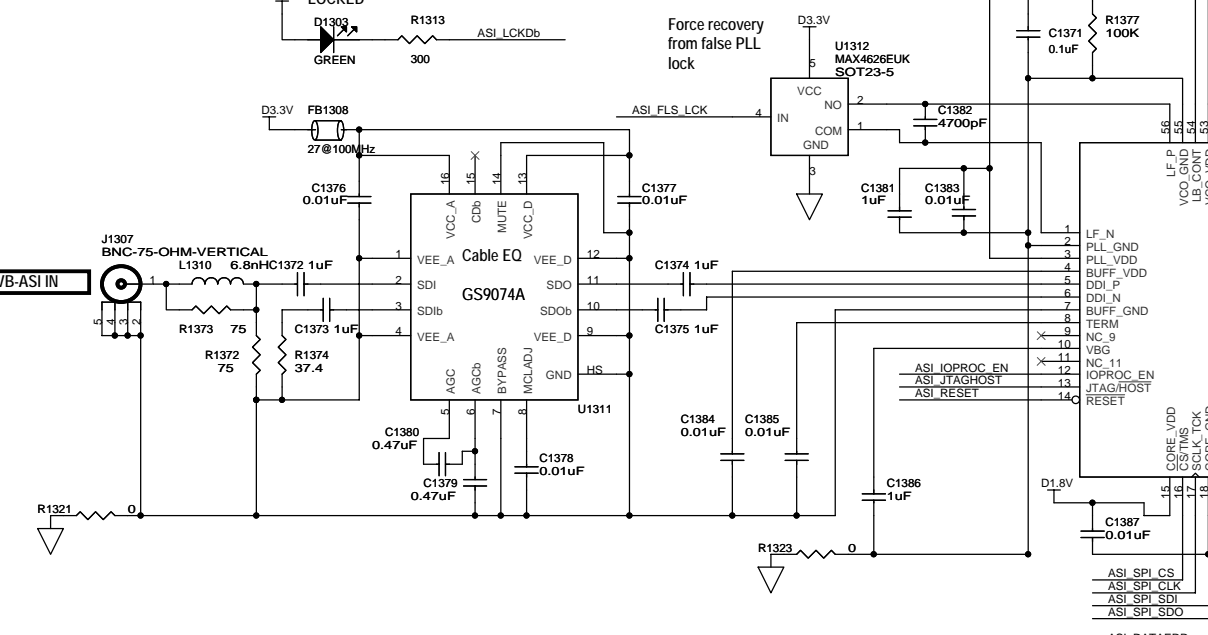
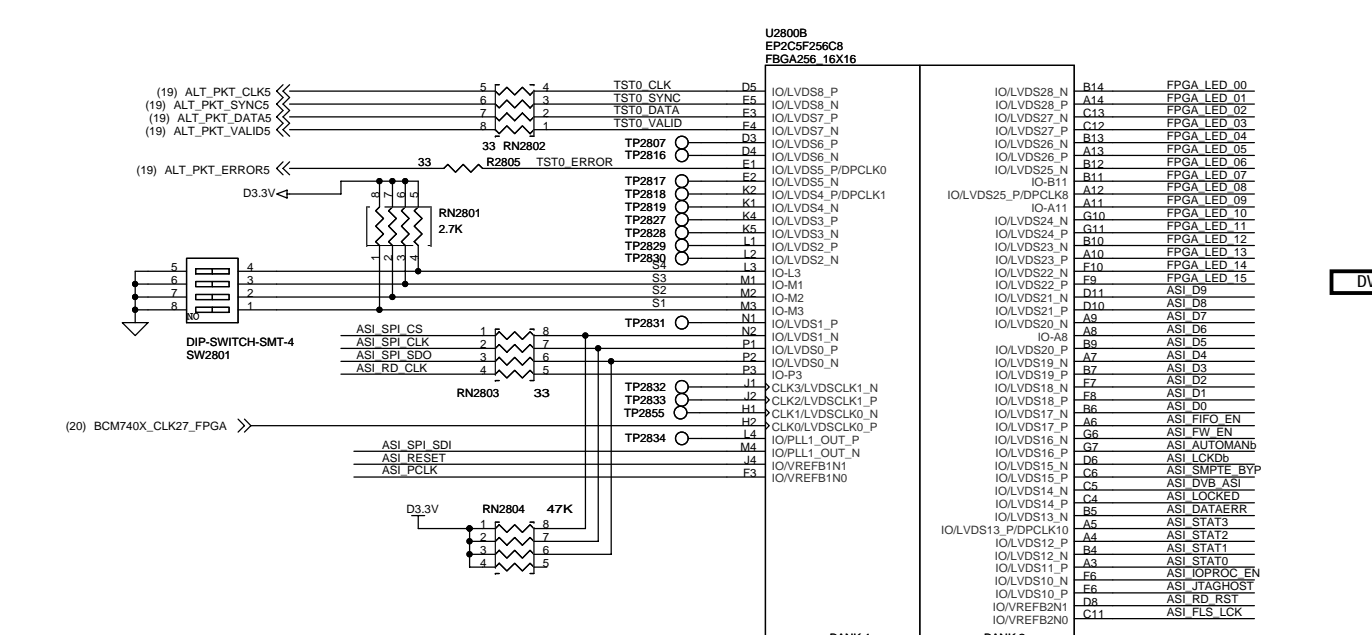
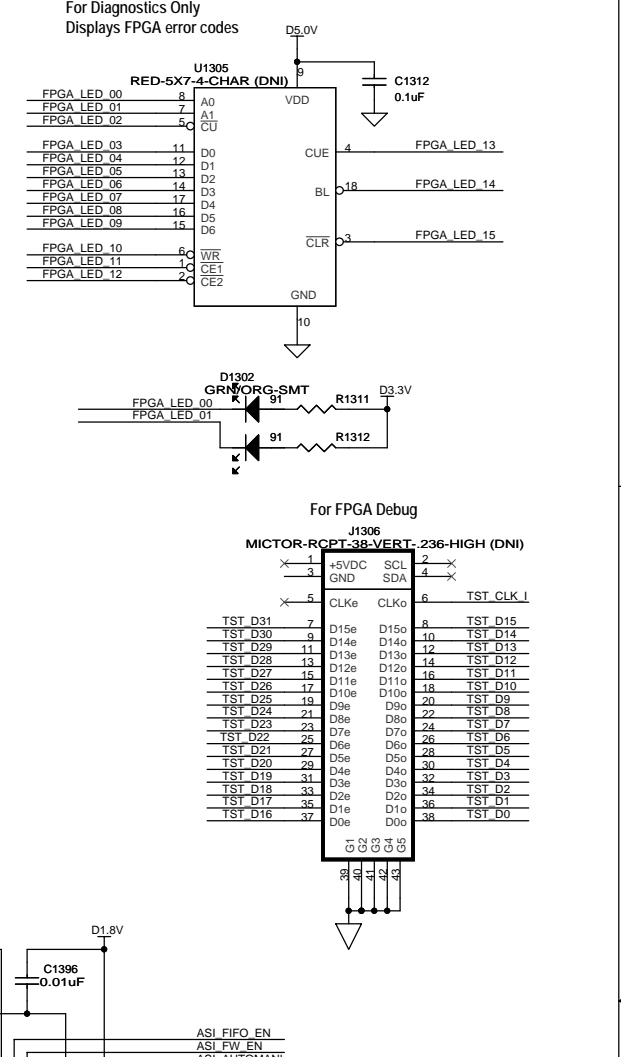
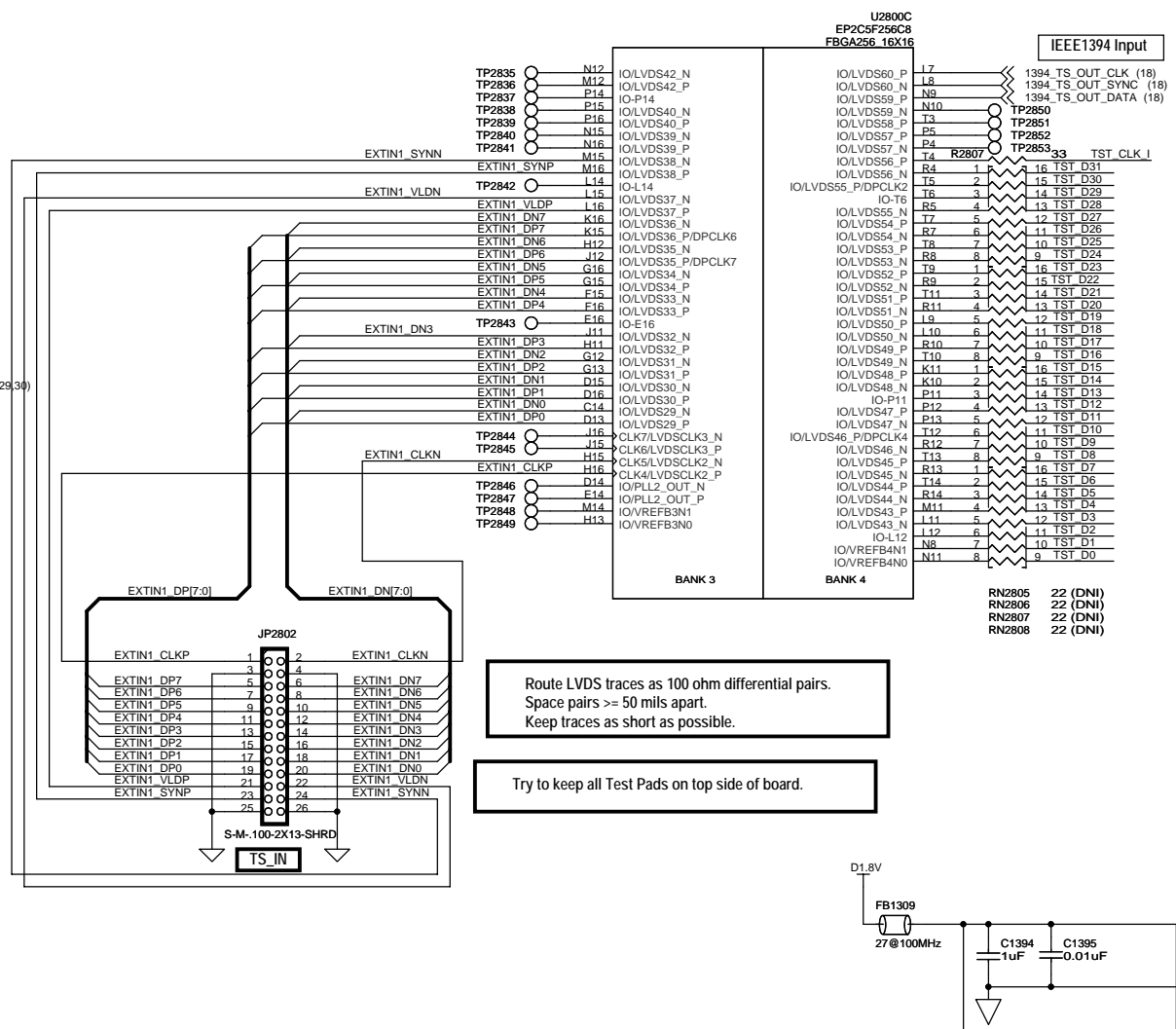
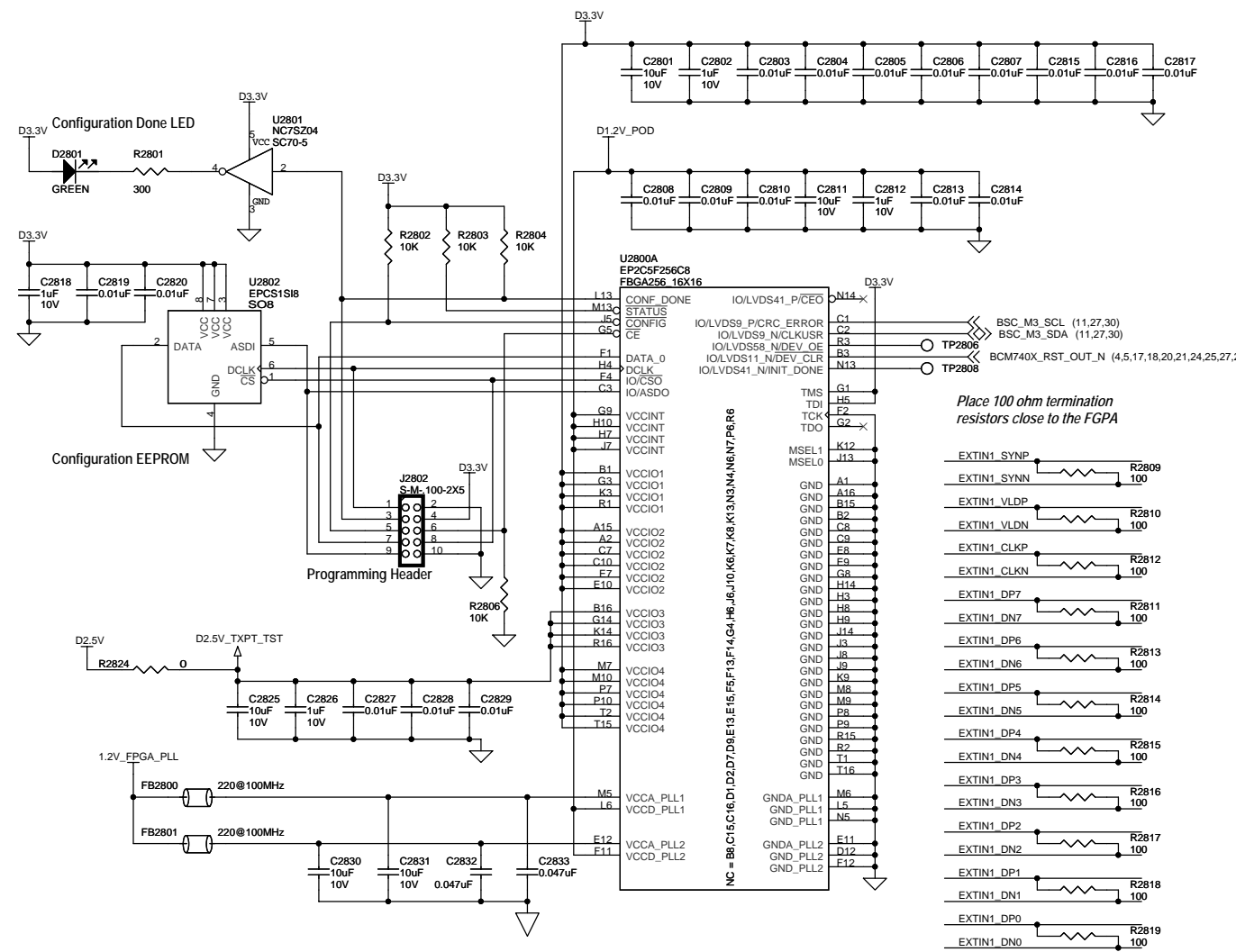
- (13) USB0\_PWRON\_N
- (13) USB1\_PWRON\_N



FrontEnd  
DaughterCard  
SLOT0

FrontEnd  
DaughterCard  
SLOT1





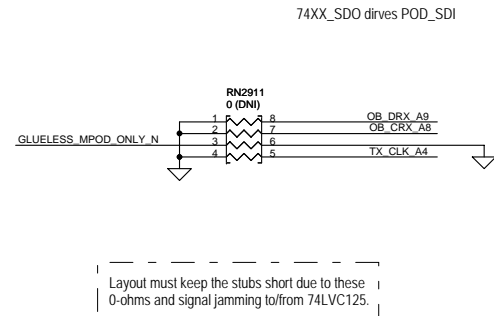
SW Setting				Selected input or function
S4	S3	S2	S1	
On	On	On	On	LVDS in
On	On	Off	On	DVB-ASI in
On	Off	On	On	IEEE-1394 in
On	Off	Off	On	Tristate TS output
On	Off	Off	Off	Clk rise at Data-Out center
On	Off	Off	Off	Clk fall at Data-Out center
On	Off	Off	Off	Clk rise at Data-In center
On	Off	Off	Off	Clk fall at Data-In center

Route LVDS traces as 100 ohm differential pairs. Space pairs >= 50 mils apart. Keep traces as short as possible.

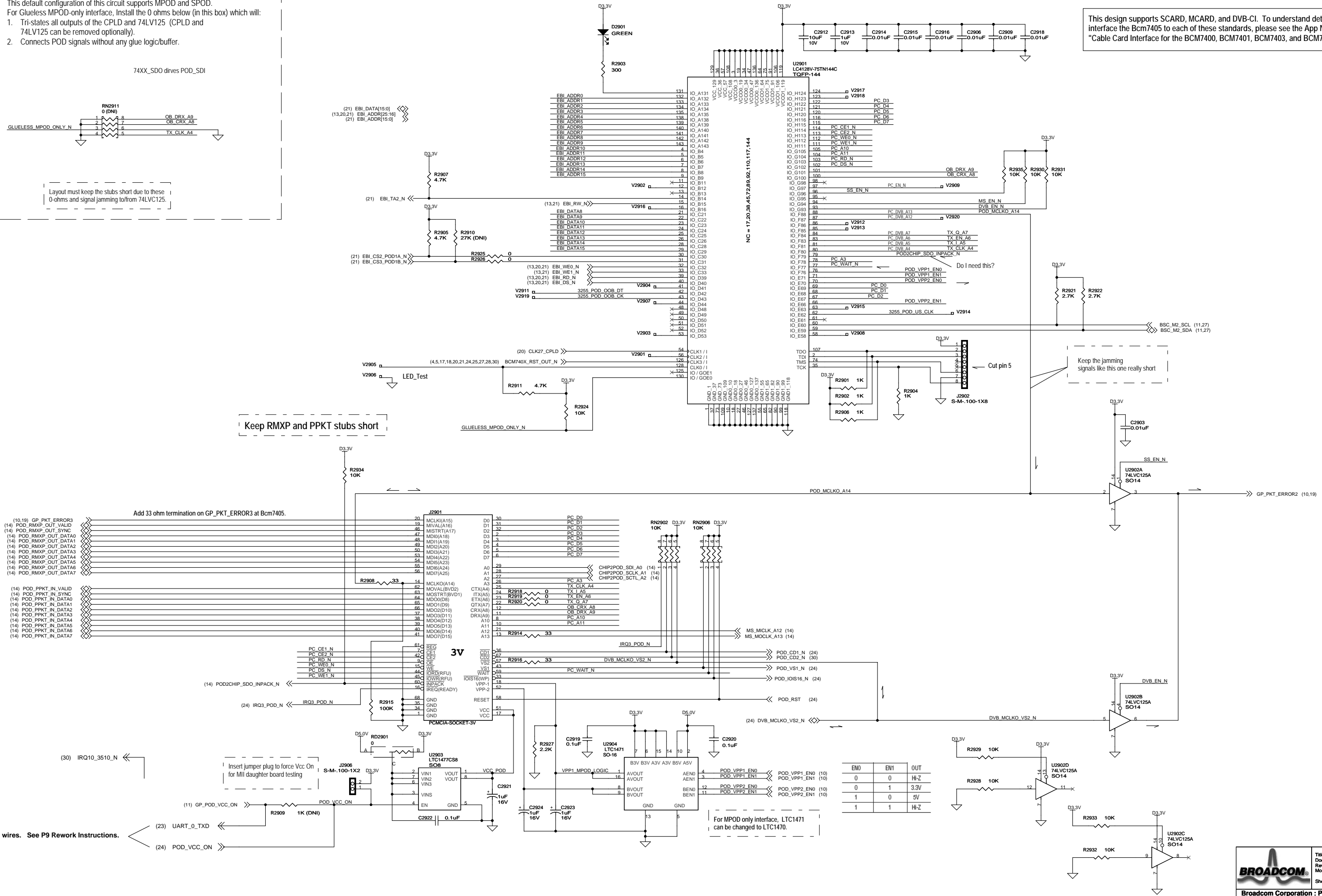
Try to keep all Test Pads on top side of board.

This default configuration of this circuit supports MPOD and SPOD. For Glueless MPOD-only interface, Install the 0 ohms below (in this box) which will:

1. Tri-states all outputs of the CPLD and 74LV125 (CPLD and 74LV125 can be removed optionally).
2. Connects POD signals without any glue logic/buffer.



This design supports SCARD, MCARD, and DVB-CI. To understand details of how to interface the Bcm7405 to each of these standards, please see the App Note "740X-AN400-Dx" "Cable Card Interface for the BCM7400, BCM7401, BCM7403, and BCM7405".



Keep RMX and PPKT stubs short

Keep the jamming signals like this one really short

Do I need this?

Add 33 ohm termination on GP\_PKT\_ERROR3 at Bcm7405.

Insert jumper plug to force Vcc On for MII daughter board testing

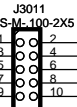
For MPOD only interface, LTC1471 can be changed to LTC1470.

ENO	EH1	OUT
0	0	Hi-Z
0	1	3.3V
1	0	5V
1	1	Hi-Z

Jumper wires. See P9 Rework Instructions.

Teletext signals are on GPIO57/58

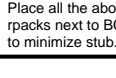
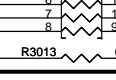
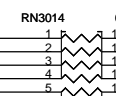
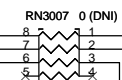
GP_VI_656_D0	GPIO_055/Ext_TP_In_23	1	GPIO_059/Ext_TP_Core_Sel_2	2
GP_VI_656_D1	GPIO_056/Ext_TP_Out_24	2	GPIO_060/Ext_TP_In_25	3
GP_VI_656_D2	GPIO_057/Ext_TP_Core_Sel_0	3	GPIO_061/Ext_TP_In_26	4
GP_VI_656_D3	GPIO_058/Ext_TP_Core_Sel_1	4	GPIO_062/Ext_TP_Out_27	5
		5	GPIO_024/Ext_TP_In_24	6
		6		7
		7		8
		8		9
		9		10



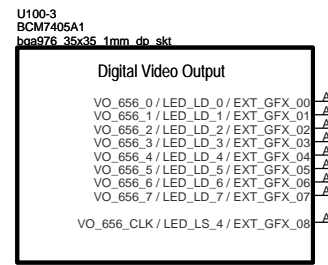
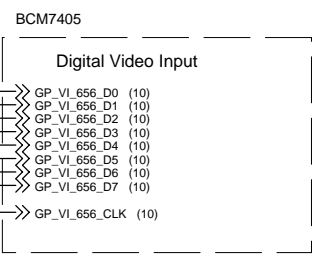
- (31) AGS\_TP\_IN24
- (31) AGS\_TP\_IN23
- (31) AGS\_TP\_OUT24
- (31) AGS\_TP\_IN25
- (31) AGS\_TP\_IN26
- (31) AGS\_TP\_OUT27

- (19) PKT\_ERROR4
- (19) PKT\_ERRORS
- (19) PKT\_VALID0
- (19) PKT\_VALID1
- (19) PKT\_VALID2
- (19) PKT\_VALID3
- (19) PKT\_VALID4
- (19) PKT\_VALID5

- (11,19) GP\_PKT\_CLK5
- (11,19) GP\_PKT\_DATA5
- (11,19) GP\_PKT\_SYNC5



Place all the above resistors and rpacks next to BCM740X to minimize stub.

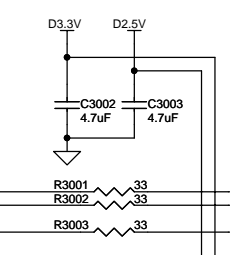
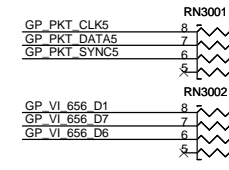
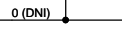


- VO\_656\_D0 (13)
- VO\_656\_D1 (13)
- VO\_656\_D2 (13)
- VO\_656\_D3 (13)
- VO\_656\_D4 (13)
- VO\_656\_D5 (13)
- VO\_656\_D6 (13)
- VO\_656\_D7 (13)
- VO\_656\_CLK (13)

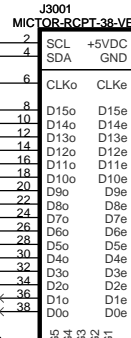
Jumper wire. See P9 Rework Instructions.

- (10) IRQ10\_3510\_N

- (11,27,28) BSC\_M3\_SCL
- (11,27,28) BSC\_M3\_SDA



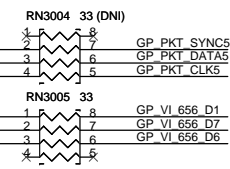
CCIR-656 VDEC-VEC-AAC-I2S Daughter Card Connector



J3001 pin36 and 38 are connected to active signals on CCIR-656 VDEC-VEC-AAC-I2S daughter card, so they cannot be used for other signals.

Signals come from CCIR-656 VDEC-VEC-AAC-I2S daughter card

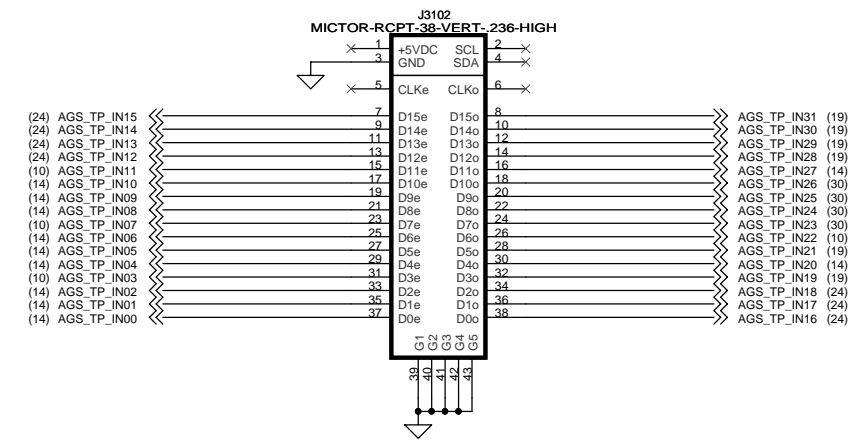
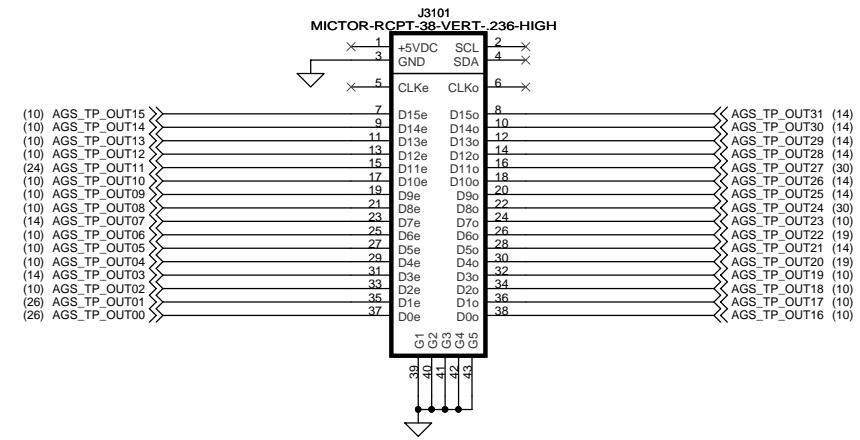
Signals go into CCIR-656 VDEC-VEC-AAC-I2S daughter card



- GP\_PKT\_SYNC5
- GP\_PKT\_DATA5
- GP\_PKT\_CLK5
- GP\_VI\_656\_D1
- GP\_VI\_656\_D7
- GP\_VI\_656\_D6

- AUD\_FS\_CLK (10)

- IRQ2\_TEST\_N (24)
- BCM740X\_RST\_OUT\_N (4,5,17,18,20,21,24,25,27,28,29)



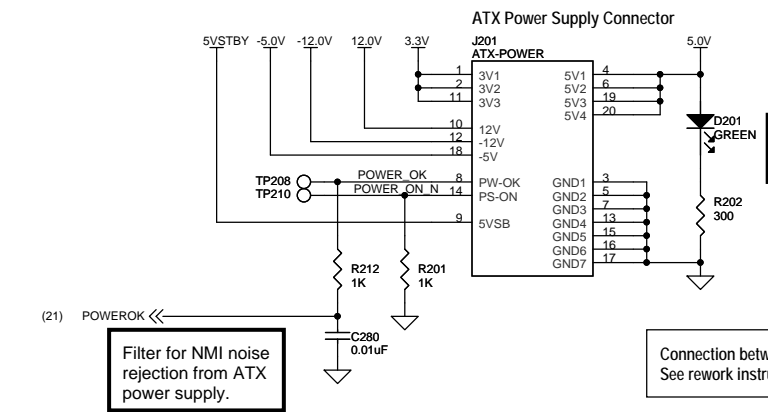
**BCM7405A0 Worst Case Power Measurements (Preliminary - sample of one)**

Voltage Rail	Supply (V)	Current (A)	Power (W)
D1.2V_BCM740X	1.2	1.60	1.920
A1.2V_BCM740X	1.2	0.42	0.504
D1.8V_BCM740X	1.8	0.88	1.584
D2.5V_BCM740X	2.5	0.19	0.475
A2.5V_BCM740X	2.5	0.14	0.350
D3.3V_BCM740X	3.3	0.02	0.066
A3.3V_BCM740X	3.3	0.25	0.825
<b>Total Power</b>			<b>5.724</b>

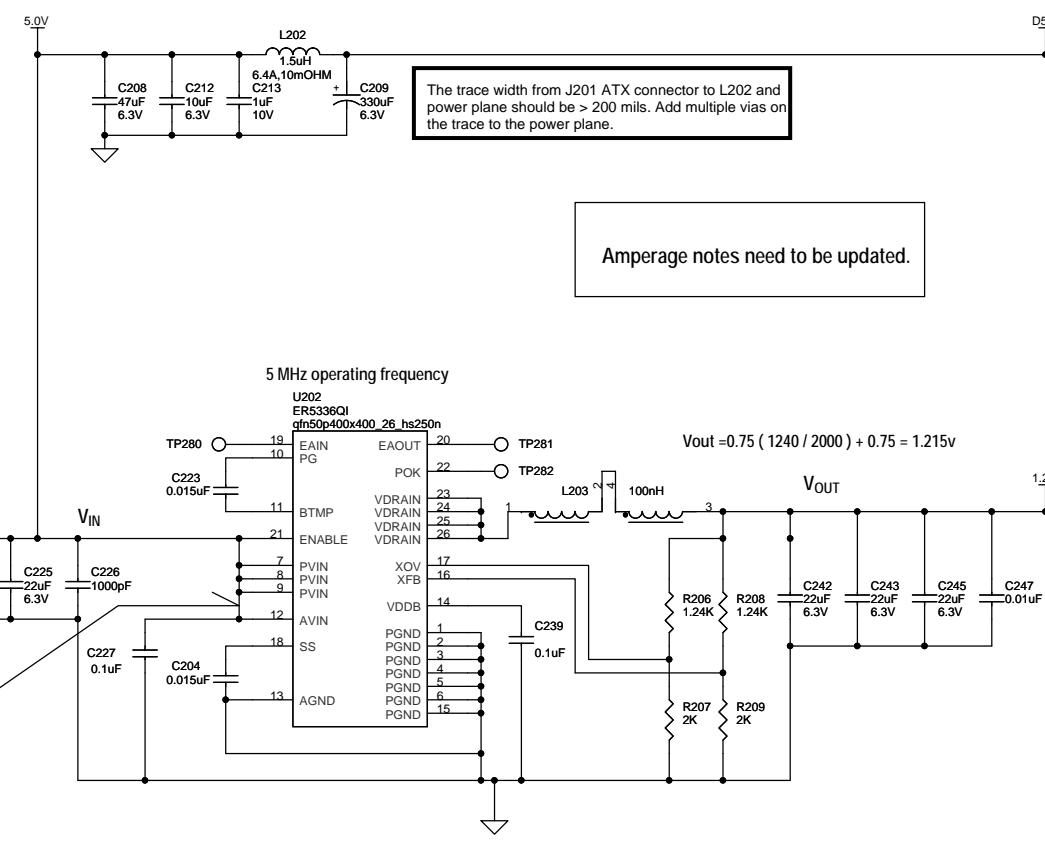
RoHS-compliant ATX Power Supply  
 BRCM P/N: 533942-00  
 Vendor: Channel Well Technology  
 Vendor P/N: PSG300C-D0-GA02-I601-0000FF

**P.S. Output**

+12V Max 18A, Min 0.3A.  
 +5V Max 35A, Min 1A.  
 +5VSB Max 2A, Min 0A.  
 +3.3V Max 28A, Min 0.3A.  
 -5V Max 0.5A, Min 0A.  
 -12V Max 1A, Min 0A.

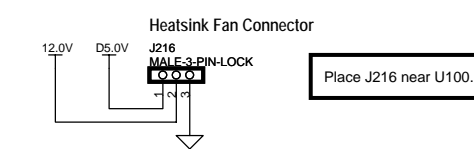
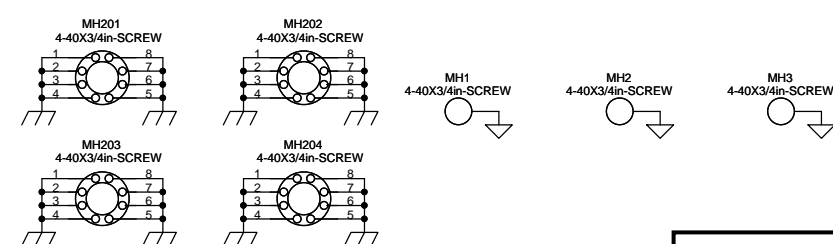
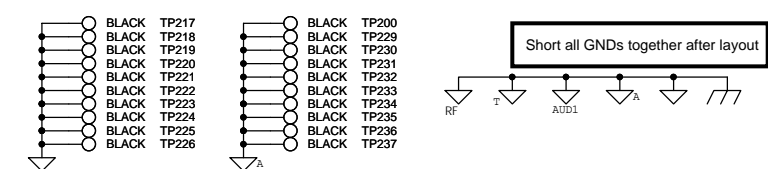
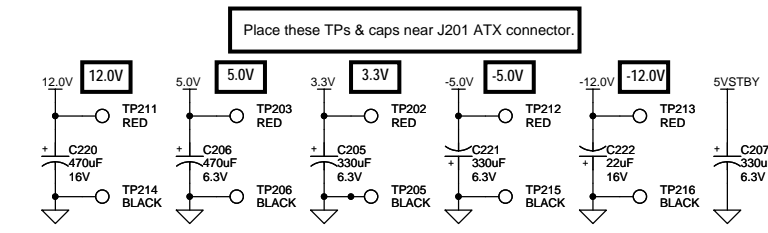


Probably could delete. Enpirion datasheet does not call for it.



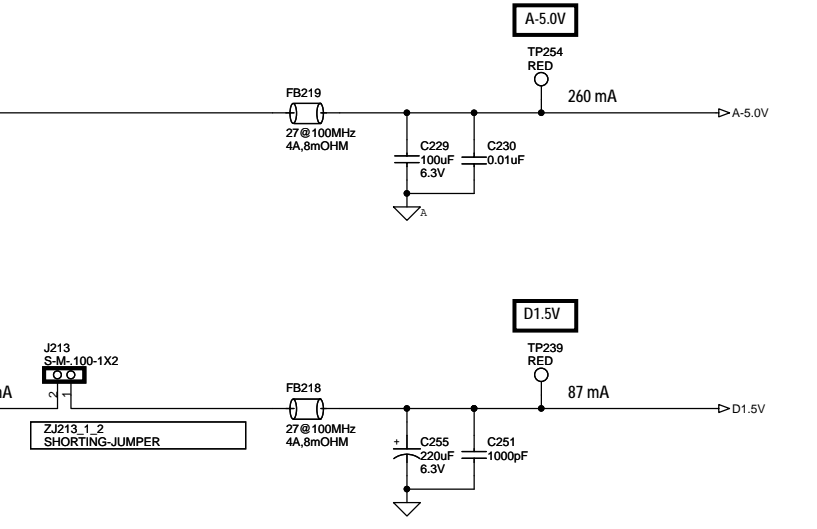
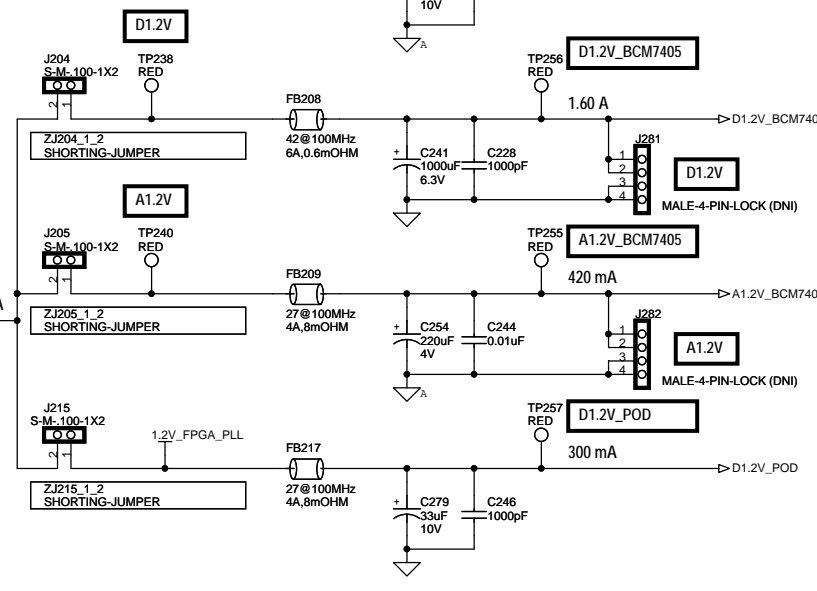
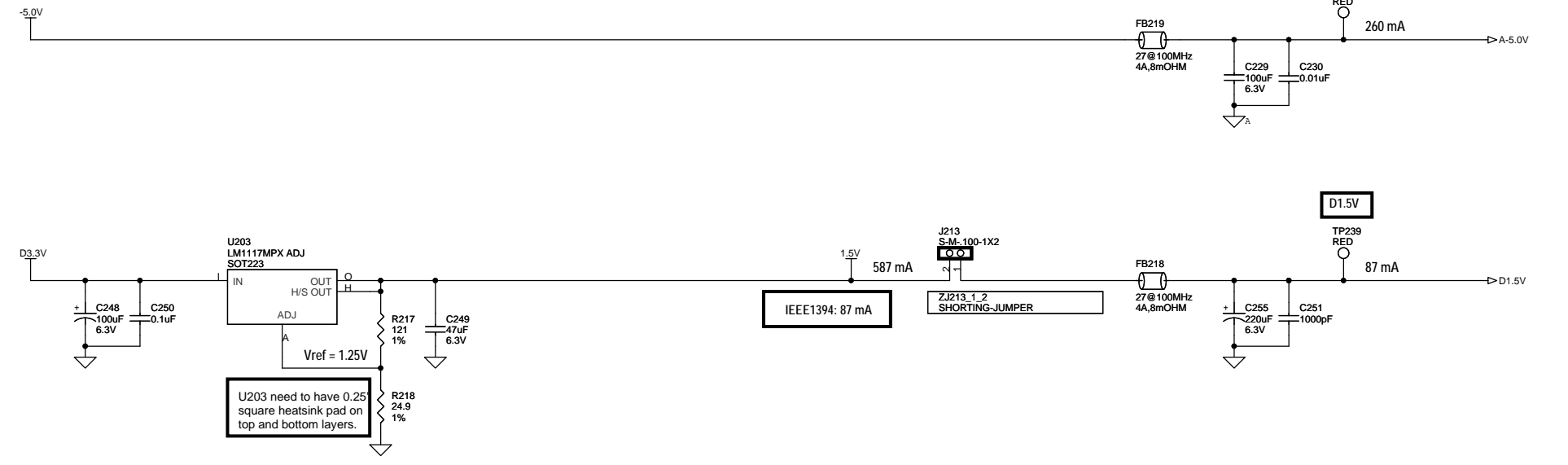
The trace width from J201 ATX connector to L202 and power plane should be > 200 mils. Add multiple vias on the trace to the power plane.

Amperage notes need to be updated.

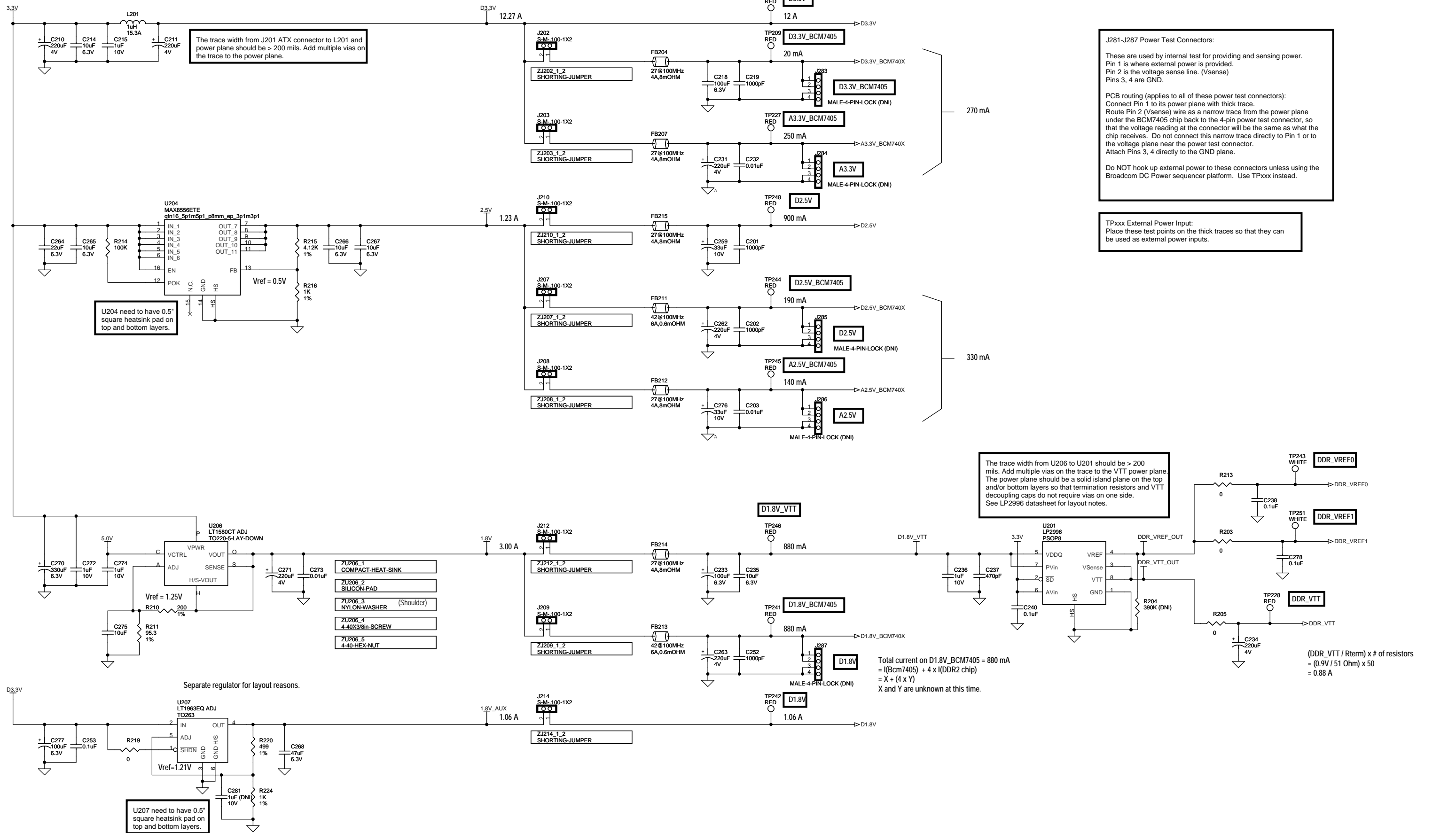


Power-up sequence is NOT required for Broadcom 65nm chip such as BCM7405. If there are other non-65nm technology based Broadcom chips used on the same board, then the board designer should follow the power-up sequence recommended by those other chips.

Board designer should check carefully and make sure if they need power-up sequence or not when designing the power supply. Inappropriate power sequences may result in chip lock-up, and/or bus contention if other output (to this chip) devices are also driving the signals during power up or down.







The trace width from J201 ATX connector to L201 and power plane should be > 200 mils. Add multiple vias on the trace to the power plane.

U204 need to have 0.5" square heatsink pad on top and bottom layers.

The trace width from U206 to U201 should be > 200 mils. Add multiple vias on the trace to the VTT power plane. The power plane should be a solid island plane on the top and/or bottom layers so that termination resistors and VTT decoupling caps do not require vias on one side. See LP2996 datasheet for layout notes.

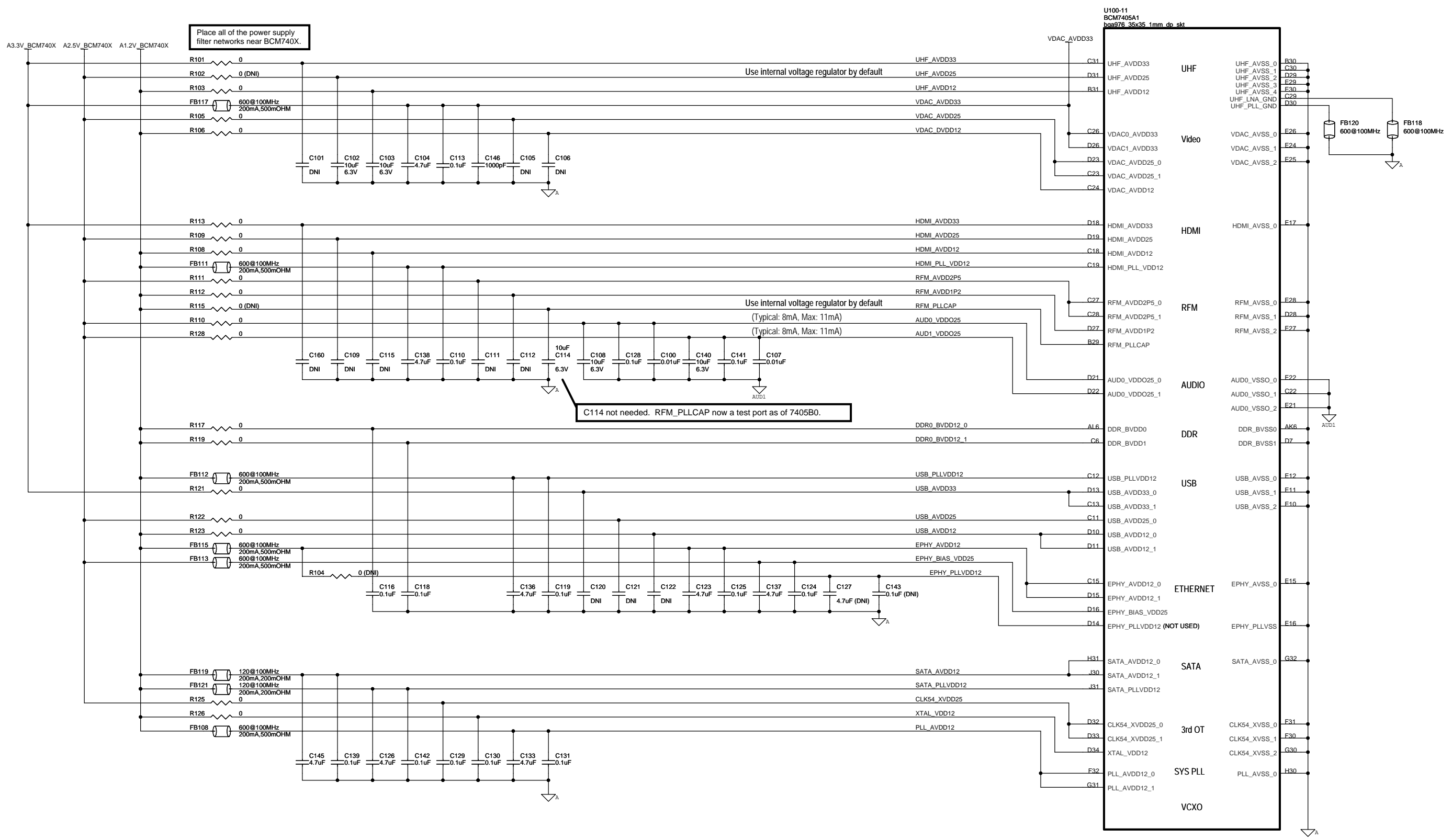
U207 need to have 0.5" square heatsink pad on top and bottom layers.

**J281-J287 Power Test Connectors:**  
 These are used by internal test for providing and sensing power. Pin 1 is where external power is provided. Pin 2 is the voltage sense line. (Vsense) Pins 3, 4 are GND.  
 PCB routing (applies to all of these power test connectors): Connect Pin 1 to its power plane with thick trace. Route Pin 2 (Vsense) wire as a narrow trace from the power plane under the BCM7405 chip back to the 4-pin power test connector, so that the voltage reading at the connector will be the same as what the chip receives. Do not connect this narrow trace directly to Pin 1 or to the voltage plane near the power test connector. Attach Pins 3, 4 directly to the GND plane.  
 Do NOT hook up external power to these connectors unless using the Broadcom DC Power sequencer platform. Use TPxxx instead.

**TPxxx External Power Input:**  
 Place these test points on the thick traces so that they can be used as external power inputs.

Total current on D1.8V\_BCM7405 = 880 mA  
 $= I(\text{Bcm7405}) + 4 \times I(\text{DDR2 chip})$   
 $= X + (4 \times Y)$   
 X and Y are unknown at this time.

$$\text{DDR\_VTT} / R_{\text{term}} \times \# \text{ of resistors} = (0.9V / 51 \text{ Ohm}) \times 50 = 0.88 \text{ A}$$



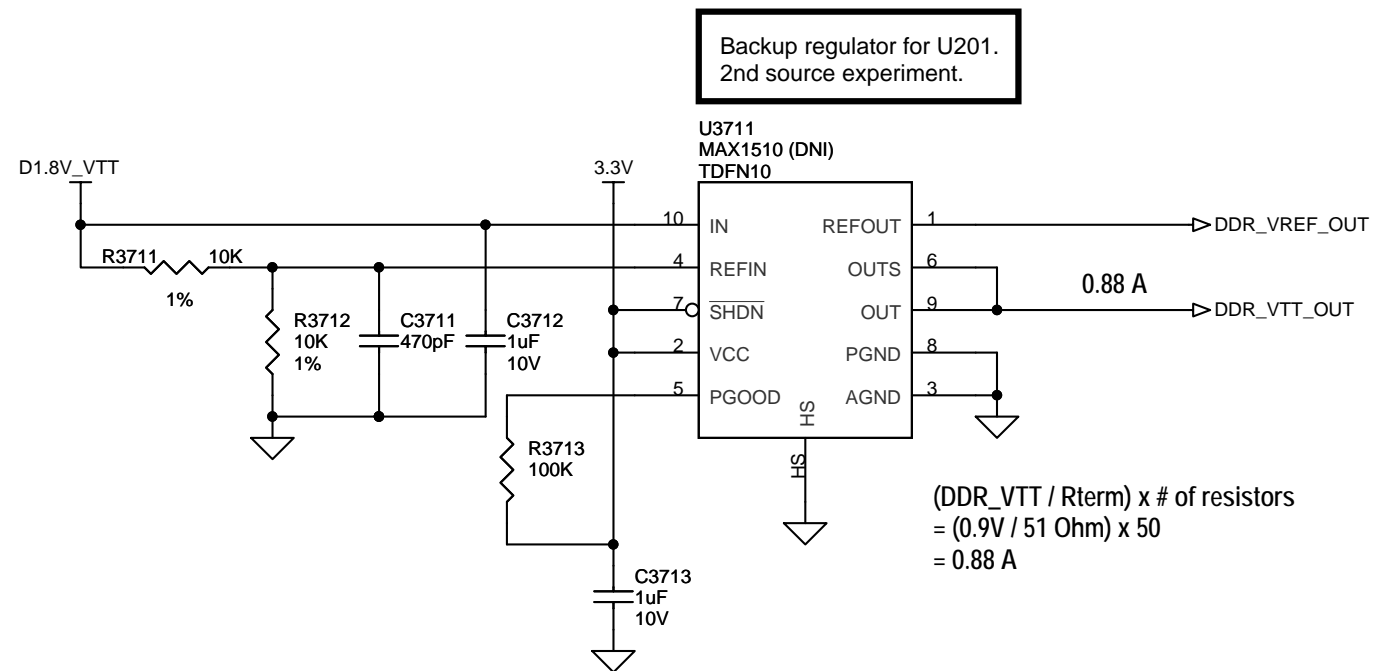
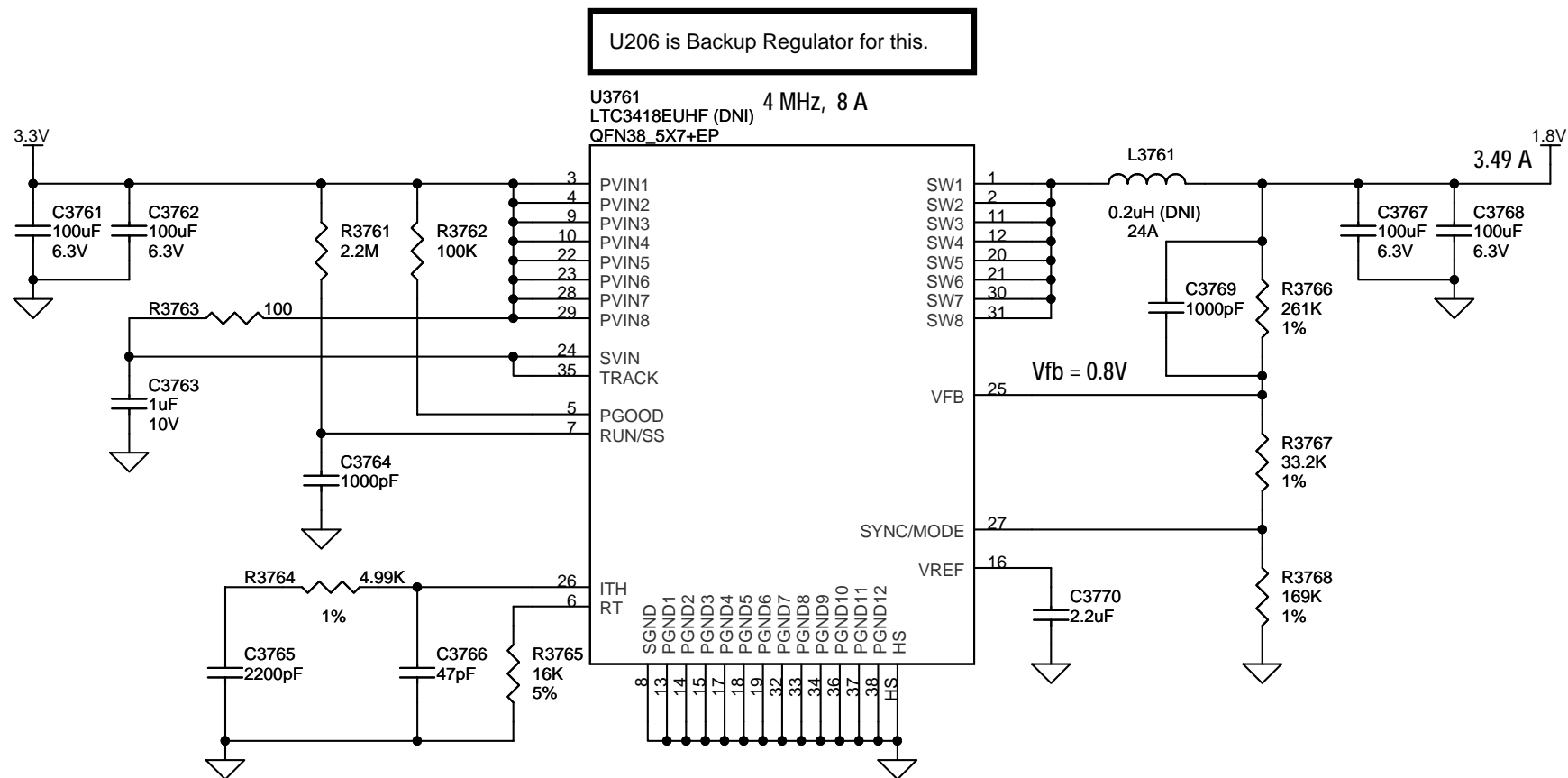
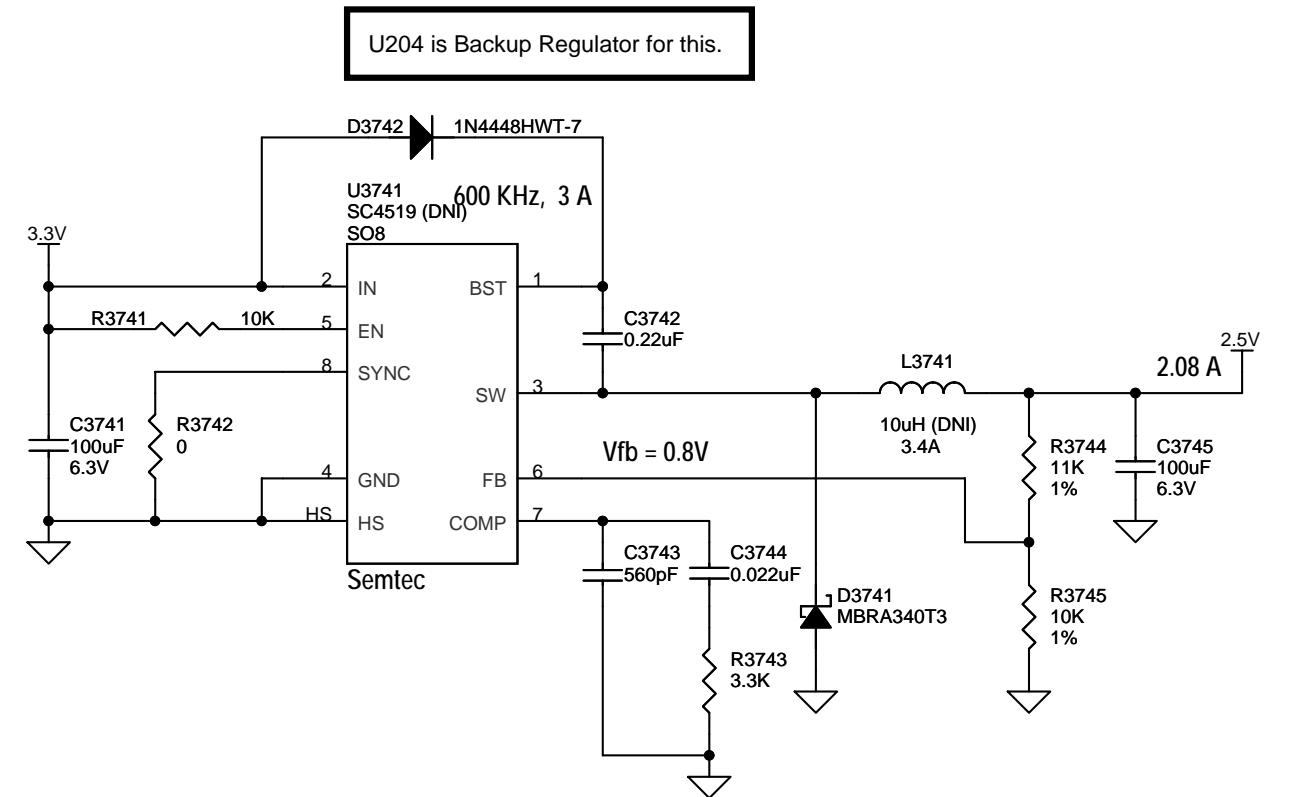
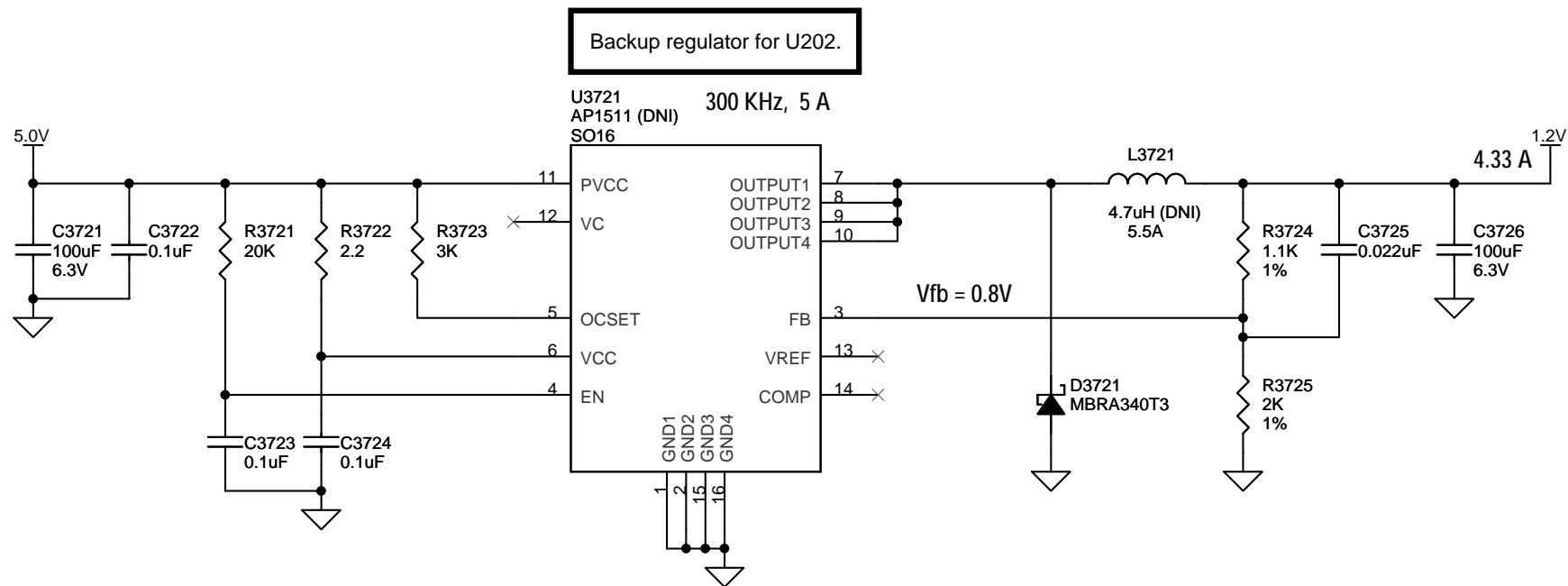


**BCM97405MBV00 PCB Stack-up and Impedance Model**

PCB Material: FR-4 170 Tg with Er (Dielectric Constant) = 4.3

Overall Thickness = 0.078 +/- 10% mils

Dielectric Thickness (mil)	Layer Definition	Copper (oz)	Target Impedance	Line / Space (mil)	Calculated Impedance	Where used
1	Top Signal	1.5 oz	50 Ohms +/- 10% differential references to layer 2	7 / 12	50.2 Ohms	DIFF_UHF_IN_P, DIFF_UHF_IN_N
			60 Ohms +/- 10% single-ended	5	59.7 Ohms	DDR_ADDR, DDR_BA, DDR_DQ, DDR_DQM, DDR_RASb, DDR_CASb, DDR_WEB, DDR_CKE, DDR_ODT
			75 Ohms +/- 10% co-planar	5.5 / 12	75.6 Ohms	CH3_4_RF_OUT, VDAC_COMP, VDAC_CHROMA, VDAC_LUMA, VDAC_RED, VDAC_GREEN, VDAC_BLUE
			90 Ohms +/- 10% differential	5.5 / 5.5	90.5 Ohms	DIFF_USBD_P/N
			100 Ohms +/- 10% differential	5 / 7	100.1 Ohms	DDR_DQS/DQSb, DDR_CK/CKb, DIFF_HDMI_P/N, DIFF_HDMI_CLKP/N, DIFF_ENET_TX_P/N, DIFF_ENET_RX_P/N, DIFF_SATA_TX_P/N, DIFF_AUD_RIGHT_P/N, DIFF_AUD0_LEFT_P/N
			110 Ohms +/- 10% differential	5 / 11.5	110 Ohms	DIFF_JEDI_TPA0P/N, DIFF_JEDI_TPB0P/N
			150 Ohms +/- 10% differential references to layer 3	5 / 20	149.8 Ohms	DIFF_RA_I1_P_C/DIFF_RA_I1_N_C, DIFF_RA_Q1_P_C/DIFF_RA_Q1_N_C, RFM_DAC_P/N
2	GND Plane	1.0 oz				
3	Signal	1.0 oz	60 Ohms +/- 10%	5	60.5 Ohms	DDR_ADDR, DDR_BA, DDR_DQ, DDR_DQM, DDR_RASb, DDR_CASb, DDR_WEB, DDR_CKE, DDR_ODT
4	Signal	1.0 oz	60 Ohms +/- 10%	5	60.5 Ohms	
5	Power Plane	1.0 oz				
6	Bottom Signal	1.5 oz	50 Ohms +/- 10% differential references to layer 2	7 / 12	50.2 Ohms	
			60 Ohms +/- 10% single-ended	5	59.7 Ohms	
			75 Ohms +/- 10% co-planar	5.5 / 12	75.6 Ohms	
			90 Ohms +/- 10% differential	5.5 / 5.5	90.5 Ohms	
			100 Ohms +/- 10% differential	5 / 7	100.1 Ohms	
			110 Ohms +/- 10% differential	5 / 11.5	110 Ohms	
			150 Ohms +/- 10% differential references to layer 3	5 / 20	149.8 Ohms	



$$(DDR\_VTT / R_{term}) \times \# \text{ of resistors} = (0.9V / 51 \text{ Ohm}) \times 50 = 0.88 \text{ A}$$



Title: Backup Power Supplies  
 Document: BCM97405MBv00 Schematic  
 Rev: Friday, February 01, 2008  
 Sheet: 37 of 37 Size: